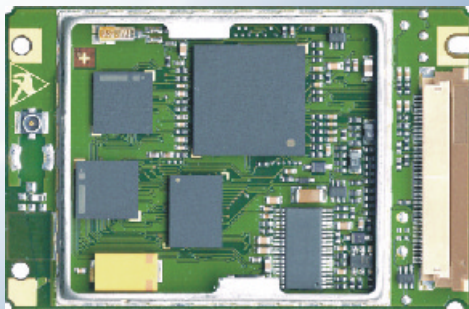


# SIEMENS

## MC35

### Siemens Cellular Engine



## Hardware Interface Description

Version: 00.20

DocID: MC35-HD-01-V00.20

Wireless Modules

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## 0 Version History

This chapter reports modifications and improvements over previous versions of the document.

Preceding document: "MC35 Hardware Interface Description" Version **00.10**

New document: "MC35 Hardware Interface Description" Version **00.20**

| Chapter         | Page         | What is new  |
|-----------------|--------------|--|
| 1.1             | 9            | Abbreviations updated  |
| 2.1             | 14           | Power consumption in SLEEP mode added (3.5mA)<br>SIM Application Toolkit added<br>Weight of module: 17g instead of 18g   |
| 3.1             | 20           | Overview of operating modes added  |
| 3.2.2           | 23           | Pin 30 (VDDL P): now $U_{IN} = 2.0\text{ V} \dots 5.5\text{ V}$ instead of $U_{IN} = 2.0\text{ V} \dots 4.8\text{ V}$  |
| 3.2.4.3         | 27           | Description of Charge-only mode added  |
| 3.3             | 28           | Power up / Power down scenarios described in more detail, figures added  |
| 3.3.1.4         | 30           | Description of Alarm mode added  |
| 3.3.2           | 31           | Summary of wake-up events added  |
| 3.3.4           | 33           | Summary of state transitions revised   |
| 3.4             | 34           | Figure 10 (RTC backup from rechargeable battery): Schematic modified - battery now connects to VDDL P  |
| 3.6             | 36           | Description of audio interface revised   |
| 3.9             | 43           | Pin 13 (VDD): $C_{load\ max,extern} = 1\mu\text{F}$ .<br>Pin 30 (VDDL P): $U_{IN} = 2.0\text{ V} \dots 5.5\text{ V}$ instead of $U_{IN} = 2.0\text{ V} \dots 4.8\text{ V}$ .<br>Pin 14 (ACCU_TEMP): NTC can be placed <i>inside or near</i> battery.<br>Pin 31 (PD): Pin is only for use in case of emergency. Frequency of watchdog signals modified.<br>Pin 32 (SYNC): Pin can be used to control a status LED.<br>Pin 34, 36 (EPPN): Parameters specified for outCalibrate = 16384. |
| 4.1 / 5.5 / 6.7 | 47 / 54 / 66 | Antenna connector: 27nH inductor for ESD protection added (figure and note)  |
| 6.1             | 59           | Supply voltage now $V_{BATT+} = 5.5$ instead of 6.0V   |
| 6.4             | 60           | Power consumption in SLEEP mode added (3.5mA)  |
| 6.6             | 65           | Receiver input sensitivity: values slightly changed  |
| 7               | 67           | MC35 specific requirements for DSB35 Support Box   |
| 8               | 70           | Information on Reference Approval added  |
| 9               | 71           | Ordering information of BB35 Bootbox and DSB35 Support Box and Siemens Car Kit added   |

## 1 Introduction

This document describes the hardware interface of the Siemens MC35 module that connects to the cellular device application and the air interface. As MC35 is intended to integrate with a wide range of application platforms, all functional components are described in great detail.

So this guide covers all information you need to design and set up cellular applications incorporating the MC35 module. It helps you quickly retrieve interface specifications, electrical and mechanical details and, last but not least, information on the requirements to be considered for integrating further components.

## 1.1 Terms and abbreviations

| Abbreviation | Description   |
|--------------|---|
| ADC          | Analog-to-Digital Converter   |
| AF           | Audio Frequency   |
| AFC          | Automatic Frequency Control   |
| AGC          | Automatic Gain Control  |
| ARP          | Antenna Reference Point   |
| ASIC         | Application Specific Integrated Circuit                                 |
| BB           | Baseband  |
| BTS          | Base Transceiver Station  |
| CB or CBM    | Cell Broadcast Message  |
| CS           | Coding Scheme   |
| CSD          | Circuit Switched Data   |
| CPU          | Central Processing Unit   |
| CTR          | Common Technical Regulation   |
| DAI          | Digital Analog Interface  |
| dBm0         | digital level, 3.14dBm0 corresponds to full scale, see ITU G.711, A-law |
| DCE          | Data Communication Equipment, Data Circuit-terminating Equipment        |
| DSB          | Development Support Box   |
| DSP          | Digital Signal Processor  |
| DSR          | Data Set Ready  |
| DTE          | Data Terminal Equipment   |
| DTR          | Data Terminal Ready   |
| DTX          | Discontinuous Transmission  |
| EFR          | Enhanced Full Rate  |
| E-GAIM       | Enhanced GSM Analog Interface Module                                    |
| EGSM         | Enhanced GSM  |
| ESD          | Electrostatic Discharge   |
| ETS          | European Telecommunication Standard                                     |
| FDMA         | Frequency Division Multiple Access                                      |
| FFC          | Flat Flexible Cable   |
| FR           | Full Rate   |
| GAIM         | GSM Analog Interface Module   |
| GMSK         | Gaussian Minimum Shift Keying   |
| GPRS         | General Packet Radio Service  |
| GSM          | Global Standard for Mobile Communications                               |

| Abbreviation | Description                                    |
|--------------|--|
| HR           | Half rate                                      |
| HW           | Hardware                                       |
| IC           | Integrated Circuit                             |
| IF           | Intermediate Frequency                         |
| IMEI         | International Mobile Equipment Identity        |
| I/O          | Input/Output                                   |
| ISO          | International Standards Organization           |
| ITU          | International Telecommunications Union         |
| kbps         | kbits per second                               |
| Li-Ion       | Lithium-Ion                                    |
| LNA          | Low Noise Amplifier                            |
| LO           | Local Oscillator                               |
| Mbps         | Mbits per second                               |
| MMI          | Man Machine Interface                          |
| MO           | Mobile Originated                              |
| MT           | Mobile Terminated                              |
| MTBF         | Mean Time Between Failures                     |
| NTC          | Negative Temperature Coefficient               |
| n.a.         | Not available                                  |
| PA           | Power Amplifier                                |
| PCB          | Printed Circuit Board                          |
| PCL          | Power Control Level                            |
| PDU          | Protocol Data Unit                             |
| PGC          | Programmable Gain-Controlled Amplifier         |
| PLL          | Phase Locked Loop                              |
| PPP          | Point-to-point protocol                        |
| PSU          | Power Supply Unit                              |
| R&TTE        | Radio and Telecommunication Terminal Equipment |
| RAM          | Random Access Memory                           |
| RF           | Radio Frequency                                |
| RI           | Ring Indication                                |
| ROM          | Read-only Memory                               |
| RMS          | Root Mean Square (value)                       |
| RTC          | Real Time Clock                                |
| Rx           | Receive Direction                              |
| SAW          | Surface Acoustical Wave Filter                 |

| Abbreviation | Description                             |
|--------------|---|
| SELV         | Safety Extra Low Voltage                |
| SIM          | Subscriber Identification Module        |
| SMS          | Short Message Service                   |
| SRAM         | Static Random Access Memory             |
| SW           | Software                                |
| TDD          | Time Division Duplex                    |
| TDMA         | Time Division Multiple Access           |
| Tx           | Transmit Direction                      |
| URC          | Unsolicited Result Code                 |
| USSD         | Unstructured Supplementary Service Data |
| VSWR         | Voltage Standing Wave Ratio             |
| ZIF          | Zero Insertion Force                    |

## 1.2 Standards

This product has been approved to comply with the following directives and standards.

### Directives

|           |   |
|-----------|---|
| 99/05/EC  | Directive of the European Parliament and of the council of 9 March 1999 on radio equipment and telecommunications terminal equipment and the mutual recognition of their conformity |
| 89/336/EC | Directive on electromagnetic compatibility  |
| 73/23/EC  | Directive on electrical equipment designed for use within certain voltage limits (Low Voltage Directive)  |

### Standards of type approval

|                     |   |
|---------------------|---|
| ETS 300 607-1       | Digital cellular telecommunications system (Phase 2); Mobile Station (MS) conformance specification; (equal GSM 11.10-1=>equal 3GPP51.010-1)  |
| EN 301 419-1        | v.4.1.1 (4-2000) Global System for Mobile communications (GSM); Harmonized standard for mobile stations in the GSM 900 and 1800 Bands covering essential requirements under article 3.2 of the R&TTE Directive (1999/5EC)(GSM 13.11)                                |
| ETS 300 342-1       | Radio Equipment and Systems(RES); Electro Magnetic Compatibility (EMC) for European digital cellular telecommunications system (GSM 900 MHz and DCS 1800 MHz) Part 1: Mobile and portable radio and ancillary equipment (for equipment for fixed and vehicular use) |
| EN 60 950           | Safety of information technology equipment  |
| ES 59005/ANSI C95.1 | Considerations for evaluation of human exposure to Electromagnetic Fields (EMFs) from Mobile Telecommunication Equipment (MTE) in the frequency range 30MHz-6GHz (relevant for applications)  |

### Requirements of quality

|              |                       |
|--------------|-----------------------|
| IEC 60068    | Environmental testing |
| DIN EN 60529 | IP codes              |

## 2 Functions

MC35 is a product variant of the well-proven TC35 dual band GSM engine. It supports all the features of TC35 and, on top, offers the advantages of the fast GPRS technology. Designed to easily provide radio connection for voice and data transmission it integrates seamlessly with a wide range of GSM/GPRS application platforms and is ideally suited to design and set up innovative cellular solutions with minimum effort.

MC35 supports GPRS multislot class 8 (4 Rx, 1 Tx time slot) and GPRS coding schemes CS-1, CS-2, CS-3 and CS-4. It operates in the frequency bands GSM 900 MHz and GSM 1800 MHz.

The complete RF part is incorporated and the GSM protocol runs autonomously on a GSM baseband processor. MC35 uses a single 40-pin ZIF connector that connects to the cellular device application. The ZIF connector establishes the application interface for control data, audio signals and power supply lines.

The cellular device application forms the Man-Machine Interface (MMI). Access to the MC35 is enabled by a serial interface (RS232).

## 2.1 MC35 key features at a glance

Table 1: MC35 key features

| Feature                       | Implementation   |
|-------------------------------|--|
| Transmission                  | Voice, Data, SMS, Fax  |
| Power supply                  | Single supply voltage 3.3V – 4.8V<br>Please refer to Chapter 6.4 for more detailed information   |
| Frequency bands               | Dual Band EGSM900 and GSM1800 (GSM Phase 2+)   |
| GSM class                     | Small MS   |
| Transmit power                | Class 4 (2W) for EGSM900<br>Class 1 (1W) for GSM1800   |
| GPRS connectivity             | GPRS multi-slot class 8<br>GPRS mobile station class B   |
| SIM card reader               | External – connected via interface connector<br>Note: The SIM card reader is not part of the MC35  |
| External antenna              | Connected via 50 Ohm antenna connector   |
| Temperature range             | Normal operation: -20°C to +55°C<br>Restricted operation: -20°C to -25°C and +55°C to +70°C<br>Storage: -40°C to +85°C   |
| Current consumption (typical) | Depending on operating mode <ul style="list-style-type: none"> <li>• TALK mode (during TX burst) at EGSM 900/1800: 2A</li> <li>• TALK mode (average) at EGSM 900/1800: 300mA / 270mA</li> <li>• IDLE mode at EGSM 900/1800: 10mA / 10mA</li> <li>• IDLE GPRS mode: 10mA</li> <li>• DATA GPRS mode at EGSM 900, multi-slot class 8, PCL 5: 360mA</li> <li>• SLEEP mode: 3.5mA</li> <li>• Power Down mode: 50µA</li> </ul> |
| Speech codec                  | Triple rate codec: <ul style="list-style-type: none"> <li>• Half Rate (ETS 06.20)</li> <li>• Full Rate (ETS 06.10)</li> <li>• Enhanced Full Rate (ETS 06.50 / 06.60 / 06.80)</li> </ul>  |
| SMS                           | MT, MO, CB, Text and PDU mode  |
| DATA                          | Transmission rates: 2.4, 4.8, 9.6, 14.4 kbps, non-transparent<br>GPRS: max. 85.6 kbps (downlink)<br>USSD<br>Coding scheme: CS 1, 2, 3, 4<br>PPP-stack  |

| Feature                 | Implementation   |
|-------------------------|--|
| FAX                     | Group 3: Class 1, Class 2  |
| Audio interface         | Analog voice: <ul style="list-style-type: none"> <li>• Microphone</li> <li>• Earpiece</li> <li>• Handsfree (supports echo cancellation and noise reduction)</li> </ul> |
| Interfaces              | RS232 (CMOS level) bi-directional bus for commands / data using AT commands  |
| Supported SIM card      | 3V/1.8V (Please note that 1.8V support requires to be separately tested and validated according to GSM 11.10)  |
| Phonebooks              | Implemented via SIM  |
| SIM Application Toolkit | Enables the SIM card to be programmed and to run additional applications such as value added services, online banking, information services etc.                       |
| Reset of MC35           | Reset via AT command or Power Down Signal  |
| Selectable baud rate    | 300bps ... 115kbps (AT interface)  |
| Autobauding range       | 1.2kbps ... 115kbps (AT interface)   |
| Firmware download       | Optionally via RS232 interface or SIM interface  |
| Real time clock         | Implemented (clock frequency 32.768kHz)  |
| Timer function          | Programmable via AT command  |
| Physical dimensions     | Size: 54.5 x 36 x 6.7mm<br>Weight: 17g   |

## 2.2 Block diagram of a GSM/GPRS application

MC35 connects to the application platform over the host interface, which takes the form of a ZIF connector. This is a data, control, audio and power supply interface. In addition, power can be supplied via contact pads located on the RF part of the MC35 PCB.

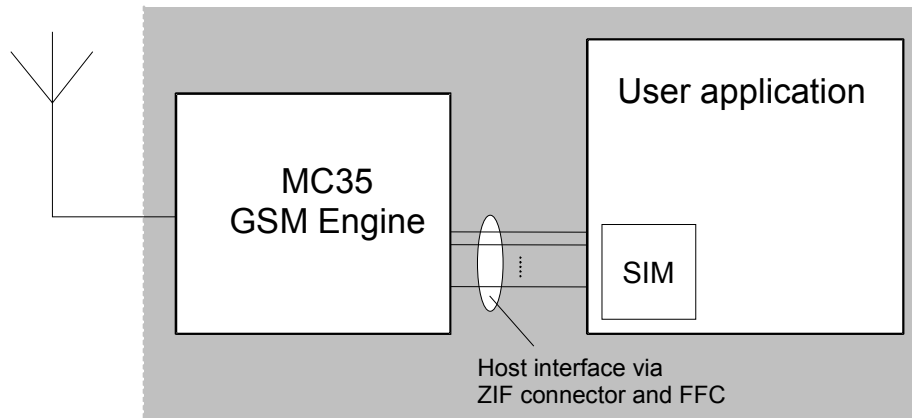


Figure 1: Overview of product concept

### 2.3 Block diagram of MC35

Figure 2 shows a block diagram of the MC35 module and illustrates the major functional components:

- GSM baseband processor
- GSM radio
- Power supply (ASIC)
- Flash
- SRAM
- ZIF connector
- Antenna connector

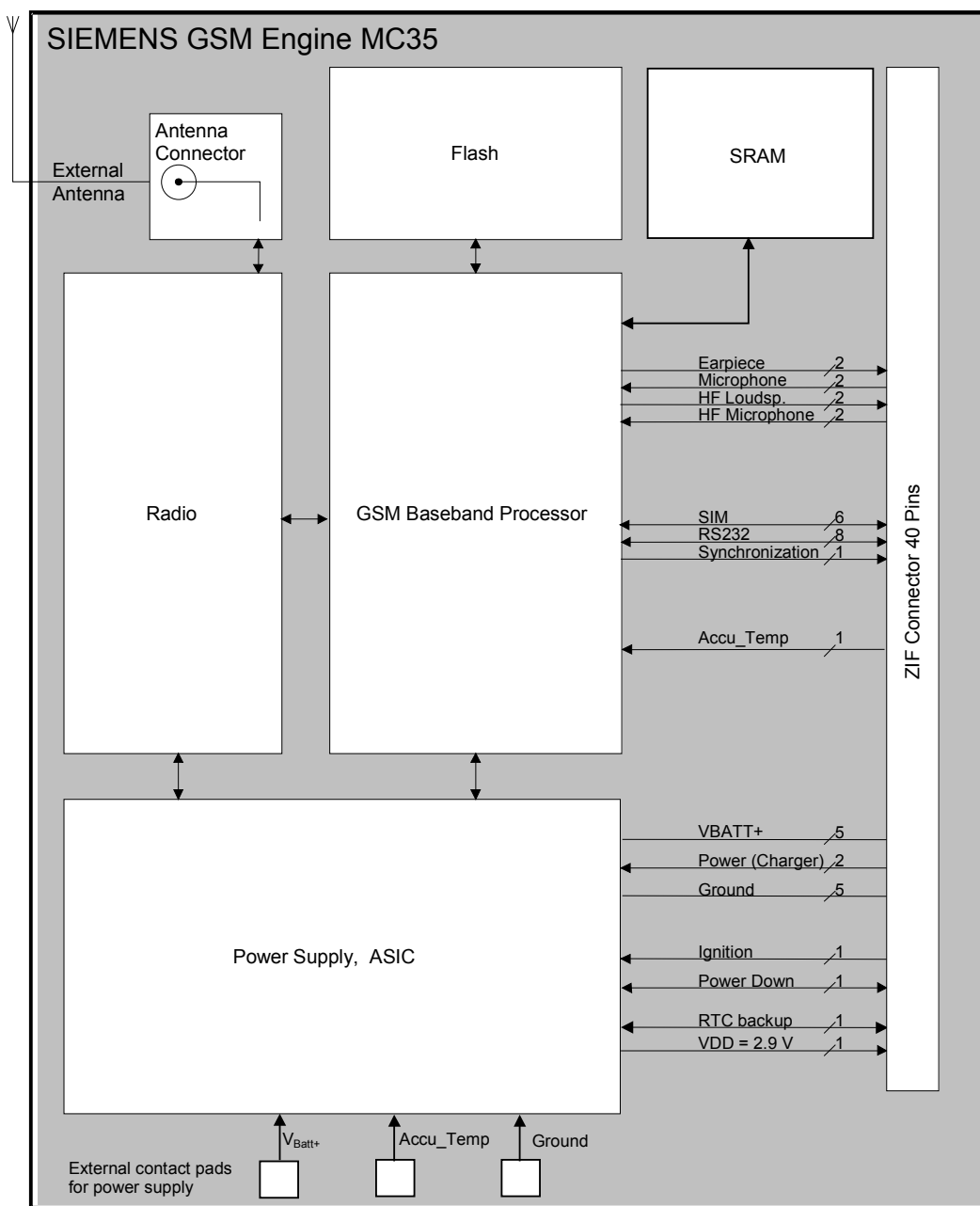
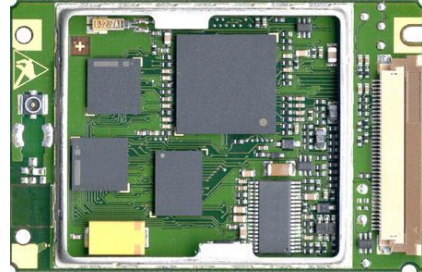


Figure 2: Block diagram of MC35

## 2.4 GSM baseband processor

The GSM baseband processor handles all the processing for audio, signal and data within a GSM cellular device. Internal software runs the application interface and the whole GSM protocol stack. A UART forms the interface to the cellular device application.

The GSM baseband processor is a single chip mixed signal baseband IC, containing all analog and digital functionality of a cellular radio. Designed to meet the increasing demands of the GSM/PCS cellular subscriber market, it supports FR, HR and EFR speech and channel coding without the need for external hardware.

Its high level of integration reduces system complexity, board dimensions and the number of components. In combination with the RF solution a complete two-chip GSM system solution is achieved, which results in extremely compact implementation, very low power consumption and cost effective system performance. Due to its very flexible interfaces the baseband controller can easily be set up to control a wide variety of RF architectures. The baseband processor is powered by a C166 CPU and a DSP processor core. Integrating these high performance processor cores with on-chip memory, a TDMA timer module and GSM specific peripherals provides a compelling single chip cellular baseband processor.

### 2.4.1 Features of the GSM baseband processor

The baseband processor includes the following major features:

- C166 MCU processor core
- Digital Signal Processing core
- On-chip MCU Program ROM / SRAM flexibly configurable as program or data RAM
- DSP Program ROM / RAM
- DSP Data ROM / RAM
- Programmable PLL for system clock generation
- GSM Timer Module that off-loads the MCU from radio channel timing
- MCU and DSP Timers
- Pulse Carry Modulation output for Automatic Frequency Correction (AFC)
- Serial RF Control Interface
- ISO 7816 compatible SIM card interface
- Digital and analog voiceband and baseband filters including digital-to-analog and analog-to-digital converters
- RF power ramping functions
- Measurement of battery voltage, battery and environment temperature
- GMSK Modulator
- Viterbi Hardware Accelerator
- A51/A52 Cipher Unit
- Comprehensive static and dynamic power management

### 3 Application Interface

MC35 is equipped with a 40-pin 0.5mm pitch ZIF connector that connects to the cellular application platform. The host interface incorporates several sub-interfaces described in the following chapters:

- Power supply and charging
- Serial interface
- Two audio interfaces
- SIM interface

Electrical and mechanical characteristics of the ZIF connector are provided in Chapter 5.4. Ordering information for the ZIF connector and the required cables are listed in Chapter 9.

### 3.1 Operating modes

The table below briefly summarizes the various operating modes referred to in the following chapters.

Table 2: Overview of operating modes

| Mode                                | Function   |   |
|-------------------------------------|--|---|
| Power Down                          | Operating voltage applied. Only a voltage regulator in the Power Supply ASIC is active for powering the RTC. Software is not active. The RS-232 interface is not accessible.   |   |
| Normal operation                    | GSM / GPRS SLEEP   | Power saving mode set by AT+CFUN command. Software is active to minimum extent. If the module was registered to the GSM network in IDLE mode, it is registered and paging in SLEEP mode, too. AT commands cannot be used. |
|                                     | GSM IDLE   | Software is active. Once registered to the GSM network, paging with BTS is carried out. The module is ready to send and receive.  |
|                                     | GSM TALK   | Connection between two subscribers is in progress. Power consumption depends on network coverage individual settings, such as DTX off/on, FR/EFR/HR, hopping sequences, antenna.  |
|                                     | GPRS IDLE  | Module is ready for GPRS data transfer, but no data is currently sent or received. Power consumption depends on network settings and GPRS configuration (e.g. multislot settings).  |
|                                     | GPRS DATA  | GPRS data transfer in progress. Power consumption depends on network settings (e.g. power control level), uplink / downlink data rates and GPRS configuration (e.g. used multislot settings).                             |
| Alarm mode                          | Restricted operation launched by RTC alert function while the module is in Power Down mode. Module will not be registered to GSM network. Limited number of AT commands is accessible.   |   |
| Charge-only                         | Limited operation for battery powered applications. Enables charging while module is detached from GSM network. Limited number of AT commands is accessible. There are several ways to launch Charge-only mode: <ul style="list-style-type: none"> <li>• From Power Down mode: Connect charger to POWER lines when engine was powered down by AT^SMSO.</li> <li>• From Normal mode: Connect charger to POWER lines, then enter AT^SMSO.</li> </ul> |   |
| Charge mode during normal operation | Normal operation (SLEEP, IDLE, TALK) and charging running in parallel. Charge mode changes to Charge-only mode when the module is powered down before charging is completed.   |   |

See also Table 7 and Table 8 for the various options of waking up MC35 and proceeding from one mode to another.

## 3.2 Power supply

The power supply of the GSM Engine MC35 has to be a single voltage source of  $V_{BATT+} = 3.3V \dots 4.8V$ . It must be able to provide a peak current of about 2A during the uplink transmission and account for drops on the VBATT+ line that may be caused in transmit bursts.

All the key functions for supplying power to the device are handled by an ASIC power supply. The ASIC provides the following features:

- Stabilizes the supply voltages for the GSM baseband using linear voltage regulators.
- Controls the module's power up and power down procedures.  
A watchdog logic implemented in the baseband processor periodically sends signals to the ASIC, allowing it to maintain the supply voltage for all MC35 components. Whenever the watchdog pulses fail to arrive constantly, the module is turned off.
- Delivers, across the VDD pin, a regulated voltage of 2.9V/70mA for the external application.

The RF power amplifier is driven directly from VBATT+.

MC35 offers two options of connecting the power supply to your application platform:

- the ZIF connector (see Chapter 3.2.2)
- or the contact pads located on the MC35 PCB (see Chapter 3.2.3).

Both options can be used in parallel.

### 3.2.1 Minimizing power losses

When designing the power supply for your application please pay specific attention to power losses. Ensure that the input voltage  $V_{BATT+}$  never drops below 3.3 V on the MC35 board, not even during transmit bursts. Also, make sure that any voltage drops that may occur during transmit bursts never exceed 400mV. It should be noted that MC35 will be switched off in the event of exceeding these limits. For further details see Chapter 6.4.

**Note:** In order to minimize power losses, use a FFC cable as short as possible. The resistance of the power supply lines on the host board and a battery pack should also be considered.

**Example:** The ZIF-FFC-ZIF connection causes a resistance of 50mΩ in the VBATT+ line and 50mΩ in the GND line, if the FFC cable reaches the maximum length of 200mm. As a result, a 2A transmit burst would add up to a total voltage drop of 200mV. Plus, if a battery pack is involved, further losses may occur due to the resistance across the battery lines and the internal resistance of the battery.

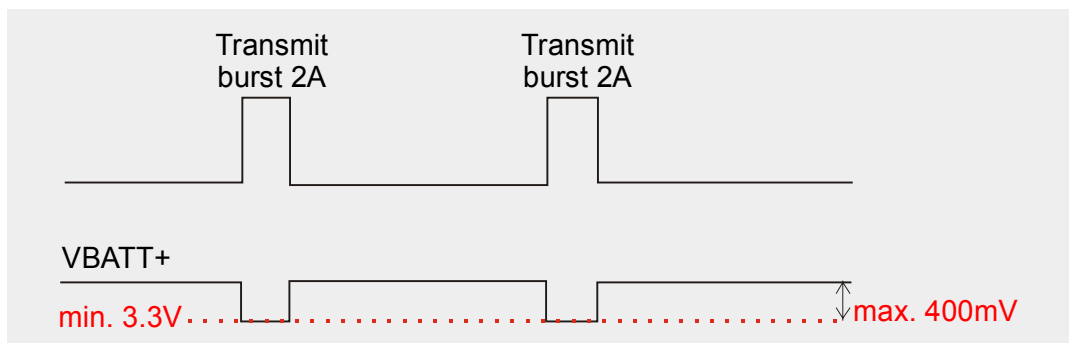


Figure 3: Power supply limits during transmit burst

### 3.2.2 Power supply across ZIF connector

10 pins of the ZIF connector are dedicated to connect the supply voltage (VBATT+) and ground (GND).

Table 3: Power supply pins of ZIF connector

| Signal name | Pin   | I/O | Description                        | Parameter   |
|-------------|-------|-----|------------------------------------|---|
| VBATT+      | 1-5   | -   | Positive operating voltage         | 3.3 V...4.8 V, $I_{max} \leq 2 \text{ A}$ @ antenna return loss $\geq 6 \text{ dB}$<br>The minimum operating voltage must not fall below 3.3 V, not even in case of voltage drop. |
| GND         | 6-10  | -   | Ground                             | 0 V   |
| POWER       | 11-12 | I   | Positive charging voltage          | $I_{max} = 500 \text{ mA}$<br>$U = 5.5...8 \text{ V}$<br>internal Pull Down $R=100\text{k}\Omega$   |
| VDDL        | 30    | I/O | Buffering of RTC (see Chapter 3.4) | $U_{OUT,max} < V_{BATT+}$<br>$U_{IN} = 2.0 \text{ V}...5.5 \text{ V}$<br>$R_i = 1\text{k}\Omega$<br>$I_{in,max} = 30\mu\text{A}$  |

### 3.2.3 Power supply across contact pads

In addition, MC35 can be powered from the contact pads located on the RF part of the PCB.

In order to connect the contact pads to your application platform it is recommended to use contact springs. A soldering connection to any of the contact pads VBATT+, GND or ACCU\_TEMP may damage MC35 and is not permitted. The position of the power pads is shown in Figure 22 and Figure 30.

Table 4: Parameters of power supply contact pads

| Signal name | I/O | Description   | Parameter   |
|-------------|-----|---|---|
| VBATT+      | -   | Positive operating voltage  | 3.3 V...4.8 V, $I_{max} \leq 2 \text{ A}$ @ antenna return loss $\geq 6 \text{ dB}$<br>The minimum operating voltage must not fall below 3.3 V, not even in case of voltage ripple. |
| GND         | -   | Ground  | 0 V   |
| ACCU_TEMP   | I   | Input for temperature measurement with NTC 10 k $\Omega$ @ 25 C to GND, $B = 3370 \text{ Kelvin} \pm 3\%$ | $U_{out} = 2.65 \text{ V}$<br>$R_i \approx 8.4 \text{ k}\Omega$   |

### 3.2.4 Battery pack

For some applications the use of a battery pack may be required. MC35 can be powered from a Li-Ion battery pack which must be specified for 3.8V, 0.85Ah and a final charge voltage of 4.2V.

To ensure reliable operation and proper charging take care that the battery pack you want to integrate into your MC35 application meets the following requirements:

- Ensure that the battery pack incorporates a protection circuit. Since charging and discharging largely depend on the battery temperature, the battery pack should include an NTC resistor. If the NTC is not inside the battery pack it must be placed nearby. The NTC resistor must be connected between ACCU\_TEMP and GND. Required NTC characteristics are:  $10k\Omega @ 25^{\circ}\text{C}$ ,  $B=3370 \text{ Kelvin } \pm 3\%$ . Please note that the NTC is indispensable for proper charging, i.e. the charging process will not start if no NTC is present.
- Furthermore, the protection circuit must be capable of detecting overvoltage (against overcharging), undervoltage (against deep discharging) and overcurrent. The circuit must be insensitive to pulse loading (see Chapter 3.2.4.1).
- On the MC35 module, a built-in measuring circuit constantly monitors the charging voltage. In the event of undervoltage, it causes MC35 to power down and automatically starts up trickle charging to protect the cell from damage. Undervoltage thresholds during the SLEEP mode are specific to the battery pack and must be evaluated for the intended model. When you evaluate undervoltage thresholds, consider both the current consumption of the MC35 and of the application circuit.
- The battery cell must be insensitive to rupture, fire and gasing under extreme conditions of temperature and charging (voltage, current).

Figure 4 shows the circuit diagram of a typical battery pack design that includes the protection elements described above.

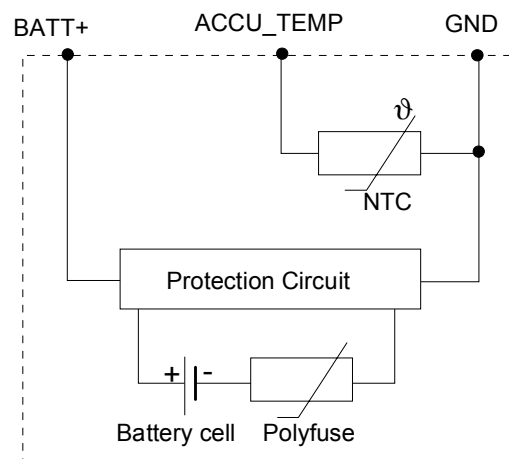


Figure 4: Battery pack

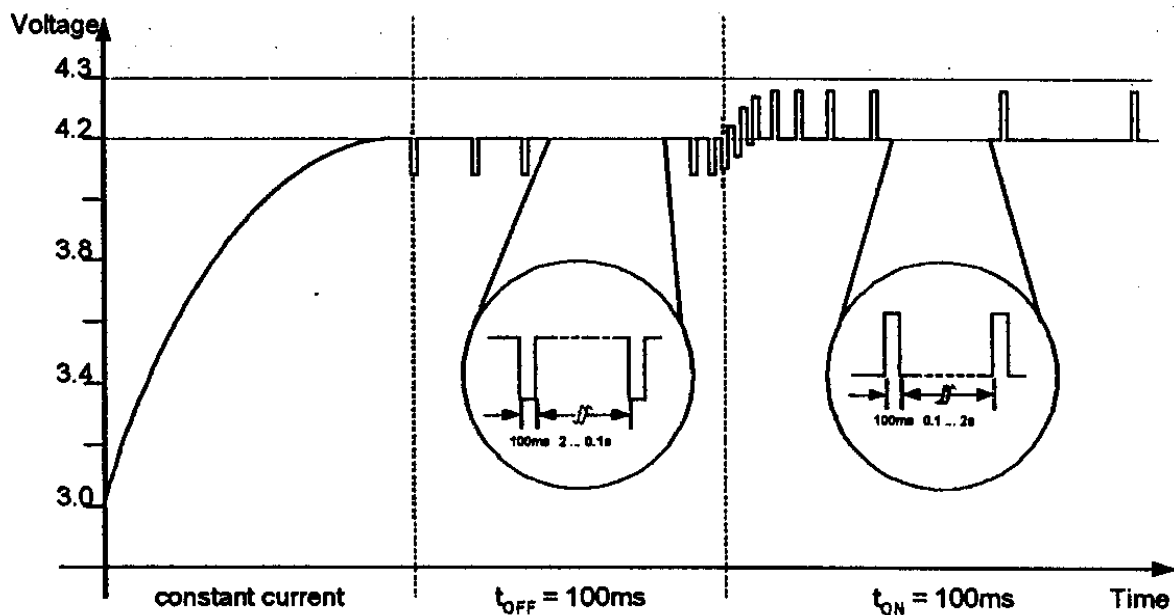
### 3.2.4.1 Supported charging technique

Charging can be accomplished only in a temperature range from 0°C to +45°C. The charging process supports trickle charging and processor controlled fast charging. In trickle mode, the battery is charged at a rate of less than 10mA. The fast charging rate provided by the charger or any other external source must be limited to 500mA. See also Table 23.

Of course, the battery can be charged regardless of the engine's operating mode. When the GSM engine is in SLEEP, IDLE or TALK mode, it remains operational while charging is in progress (provided that sufficient voltage is applied). If the charger is connected in Power Down mode (caused by AT^SMSO), the GSM engine goes into Charge-only mode.

The charge cycle begins once the charger is tied to the two POWER pins of the ZIF connector. First, the charging process goes into trickle charge mode, no matter whether the battery was deeply or partially discharged. When the battery voltage reaches 3.2V within 60 minutes, the Power ASIC turns on and wakes up the baseband processor.

Once activated, the baseband processor enables fast charging, in parallel to trickle charging. Fast charging delivers a constant current until the battery voltage reaches 4.2V and then proceeds with varying charge pulses. As shown in Figure 5, the pulse duty cycle is reduced to adjust the charging procedure and prevent the voltage from overshooting beyond 4.2V. Once the pulse width reaches the minimum of 100ms and the duty cycle does not change for 2 minutes, fast charging is completed.



### Charging Overview

Figure 5: Fast charging process

If the battery voltage fails to pass the 3.2V level within 60 minutes  $\pm 10\%$ , and consequently, processor controlled charging does not start up automatically, you have the following options:

- a) You can activate the IGT line by pulling it to ground. If the voltage is, meanwhile, above 3.0V the GSM engine proceeds to fast charging controlled by software.
- b) Driving the IGT line to ground while the voltage is still below 3.0V has no effect at all. Only trickle charging would continue. Since trickle charging may take much time (more than 60 minutes), it is recommended to manually activate software controlled charging. To do so, shortly disconnect and reconnect the charger.
- c) If no action is taken trickle charging goes on.

*Note: Do not connect the charger to the VBATT+ lines. Only the POWER lines are intended as input for charging!*

*The battery manufacturer must guarantee that the battery complies with the described charging technique. Please refer to the Application notes "Battery Pack" and "Charging the Battery Pack" for a detailed description of the charging characteristics.*

### 3.2.4.2 Charger requirements

The charger must be designed to meet the following requirements:

*a) Simple transformer power plug*

- Output voltage: 5.5V...8V (under load)
- The charge current must be limited to 500mA
- At an output voltage of 2.8V the current must never exceed 1A.
- Voltage spikes that may occur while you connect or disconnect the charger must be limited to a maximum of 25V and must not exceed 1ms.
- There must not be any capacitor on the secondary side of the power plug (avoidance of current spikes at the beginning of charging)

*b) Supplementary requirements for a) to ensure a regulated power supply*

- Output voltage: 5.5V...8V
- Current limit: 500mA
- When current is switched off a voltage peak of 10V is allowed for a maximum 1ms
- When current is switched on a spike of 1.6A for 1ms is allowed

*Note: To detect extreme thermal conditions while charging is in progress, connect a NTC (10k $\Omega$  @ 25°C, B=3370 Kelvin  $\pm 3\%$ ) from ACCU\_TEMP to GND.*

### 3.2.4.3 Operating modes during charging

While charging is in progress, the GSM engine can adopt two modes referred to as Charge mode or Charge-only mode.

|                  | How to activate mode  | Advantages   |
|------------------|---|--|
| Charge mode      | Connecting charger to the POWER lines while <ul style="list-style-type: none"> <li>GSM engine is operating, e.g. in IDLE or TALK mode</li> <li>is in SLEEP mode</li> </ul>  | <ul style="list-style-type: none"> <li>Battery can be charged while GSM engine remains operational and registered to the GSM network.</li> <li>In IDLE and TALK mode, the RS-232 interface is accessible. AT command set can be used to full extent.</li> <li>In SLEEP mode, the RS-232 interface is not accessible at all.</li> </ul> |
| Charge-only mode | Connecting charger to the POWER lines while GSM engine is <ul style="list-style-type: none"> <li>in Power Down mode (powered down by AT^SMSO)</li> <li>in Normal mode: Connect charger to POWER lines, then enter AT^SMSO.</li> </ul> | <ul style="list-style-type: none"> <li>Battery can be charged while GSM engine is deregistered from GSM network.</li> <li>Charging runs smoothly due to constant current consumption.</li> <li>The AT interface is accessible and allows to use the commands listed below.</li> </ul>  |

Once the GSM engine enters the Charge-only mode, the AT command interface presents an Unsolicited Result Code (URC) which reads:

```
^SYSSTART CHARGE-ONLY MODE
```

Note that this URC will not appear when autobauding was activated (due to the missing synchronization between DTE and DCE upon start-up). Therefore, it is recommended to select a fixed baudrate before using the Charge-only mode.

While the Charge-only mode is in progress, you can take advantage of the AT commands listed in Table 5. For further instructions refer to the AT Command Set.

Table 5: AT commands available in Charge-only mode

| AT command | Use   |
|------------|---|
| AT+CALA    | Set alarm time  |
| AT+CCLK    | Set date and time of RTC  |
| AT^SBC     | Monitor charging process<br><br>Note: While charging is in progress, no battery parameters are available. To query the battery capacity disconnect the charger.<br>If the charger connects <i>externally</i> to the host device no charging parameters are transferred to the module. In this case, the command cannot be used. |
| AT^SCTM    | Query temperature range, enable/disable URCs to report critical temperature ranges  |
| AT^SMSO    | Power down GSM engine   |

To proceed from Charge-only mode to normal operation, it is necessary to drive the ignition line to ground. This must be implemented in your host application as described in Chapter 3.3.1.1.

If your host application uses the SYNC pin to control a status LED as described in Chapter 3.8.2.2, please note that the LED is off while the GSM engine is in Charge-only mode.

### 3.3 Power up / down scenarios

#### 3.3.1 Turn on the GSM engine

MC35 can be activated in a variety of ways which are described in the following chapters:

- via ignition line IGT: starts normal operating state
- via POWER lines: starts charging algorithm
- via RTC interrupt: starts Alarm mode

##### 3.3.1.1 Turn on GSM engine using the ignition line IGT (Power on)

To switch on MC35 the IGT (Ignition) signal needs to be driven to ground level for at least 100ms. This must be accomplished with an open drain/collector driver to avoid current flowing into this pin.

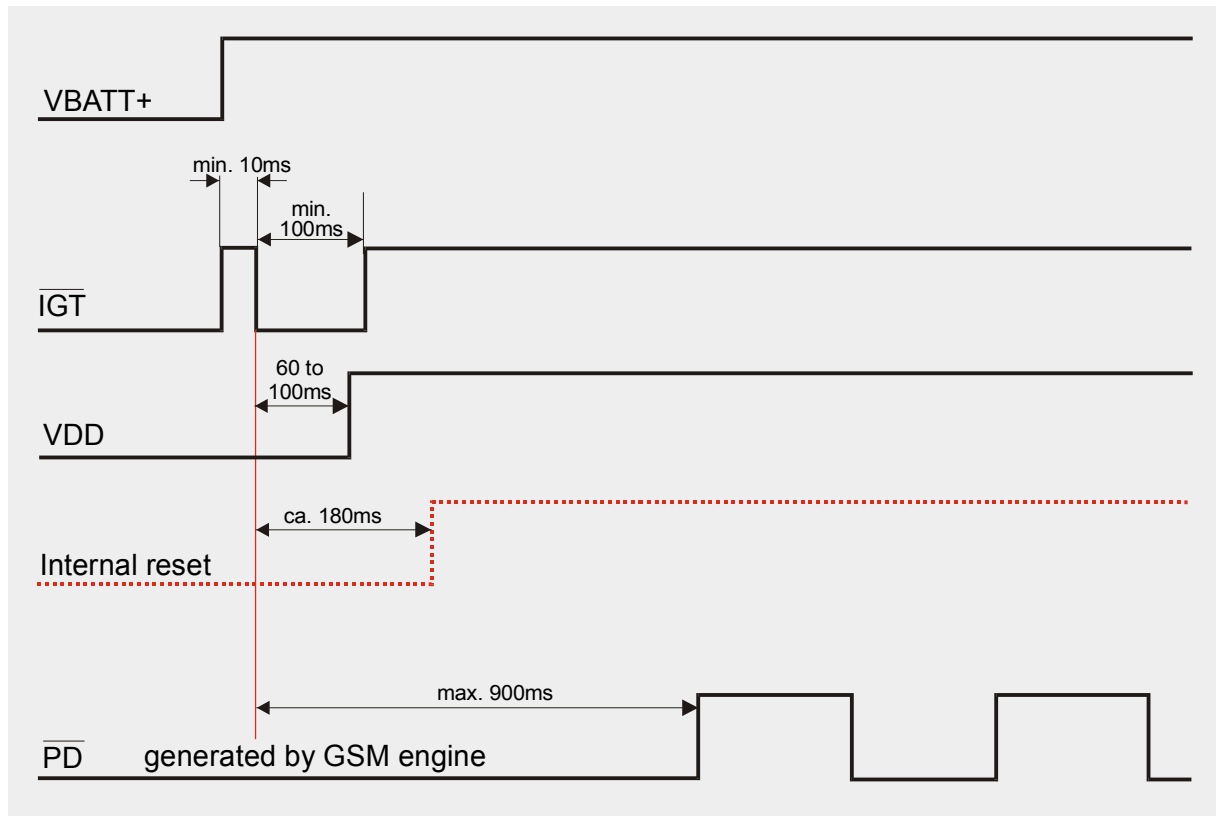


Figure 6: Power-on by ignition signal

Note: If a charger and a battery connect to the GSM engine the duration of the IGT signal must be 1s minimum.

### 3.3.1.2 Timing of the ignition process

When designing your application platform take into account that powering up MC35 requires the following steps.

- The ignition line cannot be operated until  $V_{BATT+}$  passes the level of 3.0V.
- 10ms after  $V_{BATT+}$  has reached 3.0V the ignition line can be switched low. The duration of the falling edge must not exceed 1ms.
- Another 100ms are required to power up the module.
- Ensure that  $V_{BATT+}$  does not fall below 3.0V while the ignition line is driven. Otherwise the module cannot be activated.

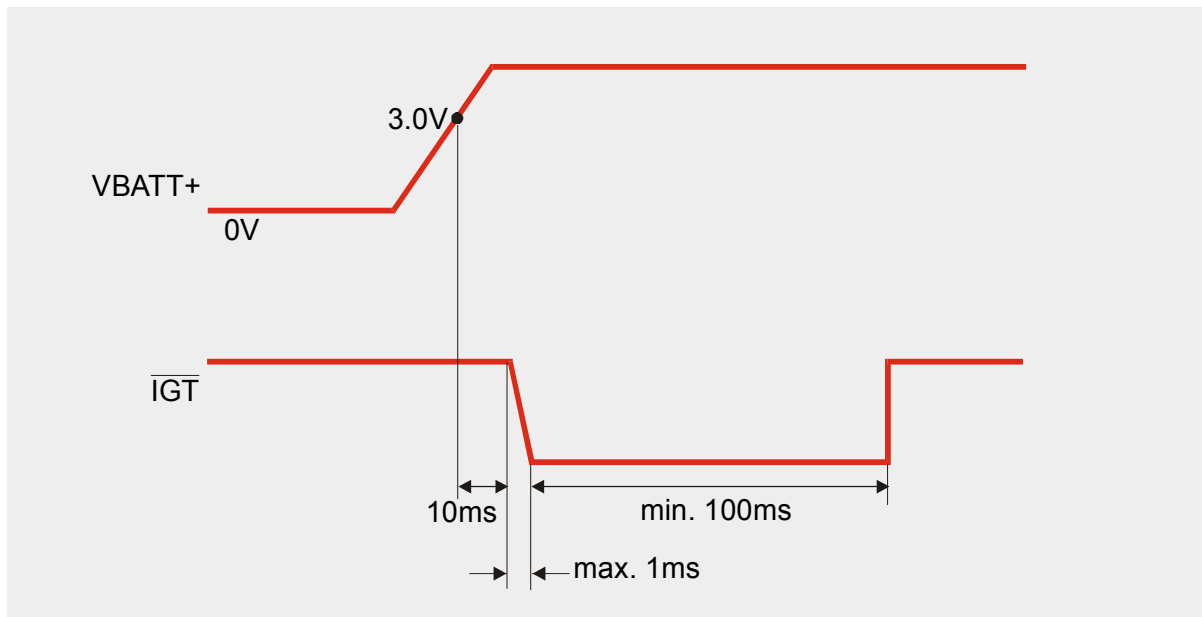


Figure 7: Timing of power-on process

### 3.3.1.3 Turn on GSM engine using the POWER lines

As detailed in Chapters 3.2.4.1 and 3.2.4.3, the charging adapter can be connected regardless of the GSM engine's operating mode. If the charger is connected to the POWER lines while the GSM engine is off, only the charging algorithm will be launched. The GSM engine runs in a restricted mode, referred to as Charge-only mode.

During the Charge-only mode the GSM engine is neither logged on to the GSM network nor is the RS-232 interface fully accessible. When the minimum voltage of 3.2V is achieved within 60 minutes and the charging process changes from trickle charging to software controlled charging. To switch to normal software mode and log on to the GSM network, the IGT line needs to be activated.

See Chapter 3.2.4.1 for a detailed description of the charge-only mode.

### 3.3.1.4 Turn on GSM engine using RTC (Alarm mode)

Another power-on approach is to use the RTC, which is constantly supplied with power from a separate voltage regulator in the power supply ASIC. The RTC provides an alert function which allows to wake up the GSM engine while power is off. To prevent the engine from unintentionally logging into the GSM network, this procedure only enables restricted operation, referred to as Alarm mode. It must not be confused with a wake-up or alarm call that can be activated by using the same AT command, but without switching off power.

Use the *AT+CALA* command to set the alarm time. The RTC retains the alarm time if the GSM engine was powered down by *AT^SMSO*. Once the alarm is timed out and executed, the GSM engine enters into the Alarm mode. This is indicated by an Unsolicited Result Code (URC) which reads:

```
^SYSSTART ALARM MODE
```

In Alarm mode only a limited number of AT commands is available. For further instructions refer to the AT Command Set.

Table 6: AT commands available in Alarm mode

| AT command     | Use  |
|----------------|--|
| <i>AT+CALA</i> | Set alarm time   |
| <i>AT+CCLK</i> | Set date and time of RTC   |
| <i>AT^SBC</i>  | Monitor charging process.<br>Note: In Alarm mode, the command lets you only check whether or not a charger is connected. The battery capacity is returned as 0, regardless of the actual voltage (since the values measured directly on the cell are not delivered to the module). |
| <i>AT^SCTM</i> | Query temperature range, enable/disable URCs to report critical temperature ranges   |
| <i>AT^SMSO</i> | Power down GSM engine  |

For the GSM engine to change from the Alarm mode to full operation (normal operating mode) it is necessary to drive the ignition line to ground. This must be implemented in your host application as described in Chapter 3.3.1.1.

If your host application uses the SYNC pin to control a status LED as described in Chapter 3.8.2.2, please note that the LED is off while the GSM engine is in Alarm mode.

### 3.3.2 Wake up GSM engine

The following table summarizes the options of waking up the GSM engine from SLEEP or Power Down mode. See also Table 8 for further information.

Table 7: Wake-up events

| GSM engine is registered to GSM network   |   |
|---|---|
| How to wake up  | From SLEEP mode   |
| Ignition line   | Not relevant  |
| RTS (falling edge)  | Yes   |
| Unsolicited Result Code (URC)   | Yes   |
| Incoming call   | Yes   |
| Incoming SMS depending on mode selected by AT+CNMI:<br>AT+CNMI=0,0 (= default, no indication upon receipt of SMS) | No  |
| AT+CNMI=1,1 (= displays URC upon receipt of SMS)  | Yes   |
| RTC alarm   | Yes   |
|   |   |
| GSM engine is detached from GSM network   |   |
| How to wake up  | From Power Down mode  |
| Ignition line   | Yes (see Chapter 3.3.1.1)   |
| RTS (falling edge)  | No  |
| Unsolicited Result Code   | No  |
| Incoming call   | No  |
| RTC alarm   | Yes, but only wake-up into Alarm mode (see Chapter 3.3.1.4)       |
| Charger to POWER lines  | Yes, but only wake-up into Charge-only mode (see Chapter 3.2.4.3) |

### 3.3.3 Turn off GSM engine

To switch the module off you can use one of the two options:

- *Normal procedure:* Software controlled by sending an AT command over the RS232 application interface. See Chapter 3.3.3.1.
- *Emergency shutdown:* Hardware driven by switching the PD (Power Down) line of the ZIF connector to ground = immediate shutdown of supply voltages, only applicable if the software controlled procedure fails! See Chapter 3.3.3.2.

#### 3.3.3.1 Turn off GSM engine using AT command

The best and safest approach to powering down MC35 is to issue the `AT^SMSO` command. This procedure lets MC35 log off from the network and allows the software to enter into a secure state and to save data before disconnecting the power supply.

If the module is in Charge Only mode (not logged into the GSM network), it switches off when the voltage is disconnected from the POWER inputs.

#### 3.3.3.2 Emergency shutdown (using PD pin)

**Caution:** Use the PD pin only when, due to serious problems, the software is not responding for more than 5 seconds. Pulling the PD pin causes the loss of all information stored in the volatile memory since power is cut off immediately. Therefore, this procedure is intended only for use in case of emergency, e.g. if MC35 fails to shut down properly.

The PD signal is available on the ZIF connector. To control the PD line it is recommended to use an open drain / collector driver. To actually turn the GSM engine off, the PD line has to be driven to ground for  $\geq 3.5$  s.

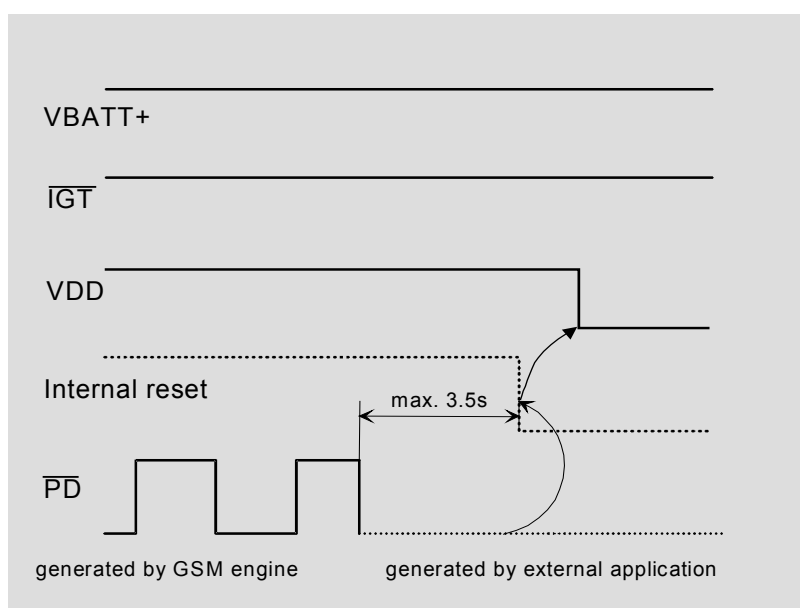


Figure 8: Deactivating GSM engine by Power Down signal

How does it work:

- Voltage VBATT+ is permanently applied to the module.
- The module is active while the internal reset signal is kept at high potential.
- The module turns off once the PD signal is grounded, the baseband processor stops sending watchdog pulses to the ASIC and the VDD line goes low.

### 3.3.4 Summary of state transitions

Table 8: State transitions of MC35

The table shows how to proceed from one mode to another (gray column = present mode, white columns = intended modes)

| Further mode →→→                                       | Power Down   | Normal mode <sup>**)</sup>  | Charge-only mode <sup>)</sup>                  | Charging in normal mode <sup>)**)</sup>                           | Alarm mode   |
|--|--|---|--|---|--|
| Present mode   |  |   |  |   |  |
| Power Down mode <u>without</u> charger                 | ---  | IGT >100 ms at low level  | Connect charger to POWER (high level at POWER) | No direct transition, but via "Charge-only mode" or "Normal mode" | Wake-up from Power Down mode (if activated with AT+CALA) |
| Power Down mode with charger (high level at POWER pin) | ---  | IGT (if supply voltage is above 3.0V). No automatic transition, but via Power Down mode without charger | 100ms < IGT < 500ms at low level               | IGT >1 s at low level   | Wake-up from Power Down mode (if activated with AT+CALA) |
| Normal mode <sup>**)</sup>                             | AT^SMSO <u>or</u> exceptionally PD pin > 3.5 s at low level  | ---   | No automatic transition, but via "Power Down"  | Connect charger to POWER (high level at POWER)                    | AT+CALA followed by AT^SMSO                              |
| Charge-only mode <sup>)</sup>                          | Disconnect charger (POWER at low level) <u>or</u> AT^SMSO <u>or</u> exceptionally PD pin >3.5 s at low level | No automatic transition, but via "Charge in Normal mode"  | ---  | IGT >1 s at low level   | No direct transition                                     |
| Charging in normal mode <sup>)**)</sup>                | Via "Charge-only mode" <u>or</u> exceptionally PD pin > 3.5 s at low level                                   | Disconnect charger from POWER   | AT^SMSO  | ---   | No direct transition                                     |
| Alarm mode   | AT^SMSO <u>or</u> exceptionally PD pin > 3.5 s at low level  | IGT >100 ms at low level  | Connect charger to POWER (high level at POWER) | No direct transition, but via "Charge-only mode" or "Normal mode" | ---  |

<sup>)</sup> See Chapter 3.2.4.1 for details on the charging mode

<sup>\*\*)</sup> Normal mode covers TALK, IDLE and SLEEP modes

### 3.4 RTC backup

The internal Real Time Clock of MC35 is supplied from a voltage regulator of the power supply ASIC which is also active when MC35 is powered down. An alarm function is provided for activating and deactivating MC35.

In addition, you can use the VDDL P pin on the ZIF connector (pin no. 30) to backup the RTC from an external capacitor or a battery (rechargeable or non-chargeable). The capacitor is charged by the VBATT+ line of MC35. If the voltage supply at VBATT+ is disconnected the RTC can be powered by the capacitor. The size of the capacitor determines the duration of buffering when no voltage is applied to MC35, i.e. the greater capacitor the longer MC35 will save the date and time.

A serial resistor placed on the board next to VDDL P limits the input current of an empty capacitor. This eliminates the need of adding a resistor as required on TC35 or TC37 applications.

The following figures show various sample configurations. The voltage applied at VDDL P can be in the range from 2 to 5.5V. Please refer to Table 14 for the parameters required.

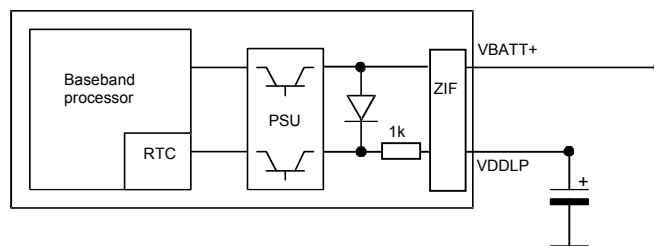


Figure 9: RTC supply from capacitor

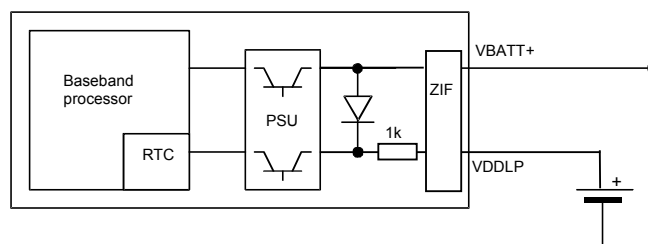


Figure 10: RTC supply from rechargeable battery (accumulator)

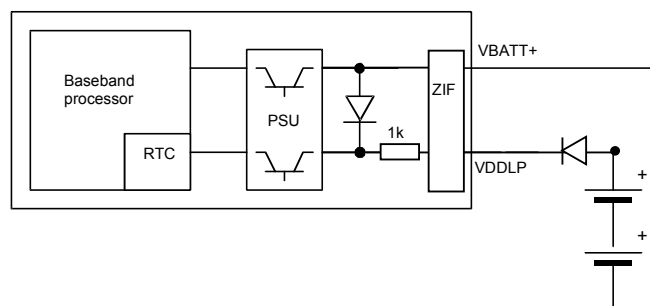


Figure 11: RTC supply from non-chargeable battery

### 3.5 Serial interface

This chapter describes the data interface of the MC35 GSM Engine. The data interface operates at CMOS level (2.65V).

*Note: The MC35 GSM engine is connected like a DCE:*  
TxD MC35 receives data from TxD Application  
RxD MC35 sends data to RxD Application

*All RS232 signals on the ZIF connector are low active!*

An overview of the data interface signals is given in *Figure 12*.

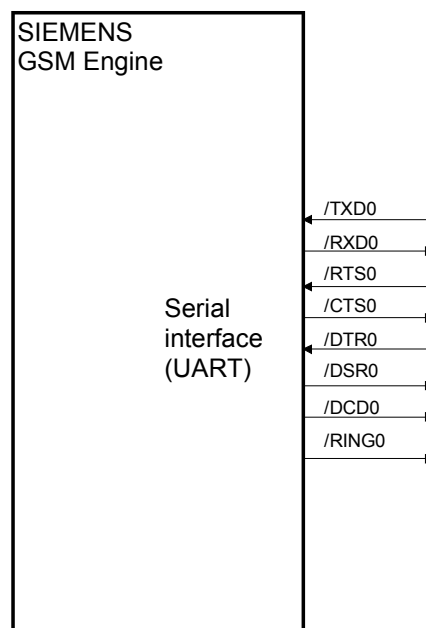


Figure 12: RS232 interface

The data interface is implemented as a serial asynchronous transmitter and receiver conforming to ITU-T RS232 Interchange Circuits DCE. It has fixed parameters of 8 data bits, no parity and 1 stop bit, and can be selected in the range of 1.2kbps up to 115kbps for autobauding and in the range of 300baud to 115kbps for manual settings. Hardware handshake using signals RTS0 / CTS0 and software flow control via XON/XOFF are supported.

In addition, the modem control signals DTR<sup>\*)</sup>, DSR0, DCD0 and RING0 are available. The modem control signal RING0 (Ring Indication) is supported to indicate an incoming call to the cellular device application. There are different modes of operation, which are software-selectable (AT commands).

<sup>\*)</sup> **The DTR0 signal will only be polled once per second from the internal firmware of MC35 !**

### 3.6 Audio interface

MC35 comprises two audio interfaces, each with an analog microphone input and an analog earpiece output (see block diagram below).

To suit several types of equipment, there are six audio modes available which can be selected with the AT^SNFS command. The electrical characteristics of the voiceband part vary with the audio mode. For example, sending and receiving amplification, sidetone paths, noise suppression etc. depend on the selected mode and can be set with AT commands (except for mode 1).

Please refer to Chapter 6.5 for specifications of the audio interface and an overview of the audio parameters. Detailed instructions on using AT commands are presented in the "MC35 AT Command Set". Table 25 on page 62 summarizes the characteristics of the various audio modes and shows what parameters are supported in each mode.

The first audio interface can be set to the audio modes 1 (default), 4 and 5. The default configuration is optimized for the Votronic HH-SI-30.3/V1.1/0 handset and used for type approving the Siemens reference configuration. Audio mode 1 has fix parameters which cannot be modified. In audio mode 4, you can avail of AT commands to adjust the Votronic handset as well as any individual handset.

The second audio interface is especially intended for headsets and can be configured to the audio modes 2, 3 or 6. In order to integrate a handsfree application you can take advantage of the Siemens Car Kit Portable and connect it to the second interface.

All microphone inputs and the earpiece / headset outputs are balanced. A power supply for electret microphones is implemented and can be used with in audio modes 1 to 4. If not needed, it has to be decoupled with capacitors.

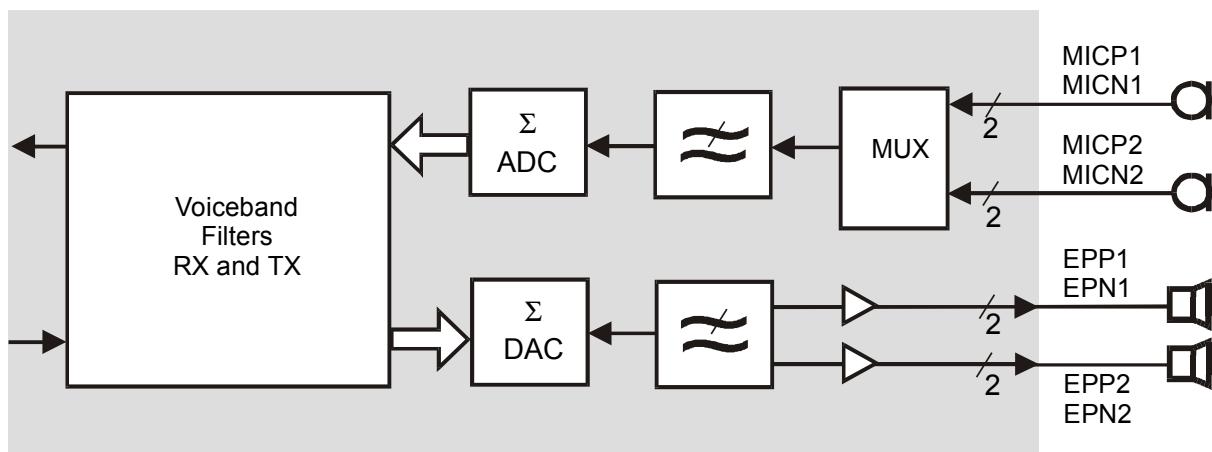


Figure 13: Audio block diagram

### 3.6.1 Speech processing

The voiceband filter includes a digital interpolation low-pass filter for received voiceband signals with digital noise shaping and a digital decimation low-pass filter for voiceband signals to be transmitted.

After voiceband (interpolation) filtering the resulting 2Mbit/s data stream is digital-to-analog converted and amplified by a programmable gain stage in the voiceband processing part. The output signal can directly be connected to the earpiece of the GSM cellular device or to an external headset earpiece (via I/O connector). In the opposite direction the input signal from the microphone is first amplified by a programmable amplifier. After analog-to-digital conversion a 2Mbit/s data stream is generated and voiceband (decimation) filtering is performed.

The resulting speech samples from the voiceband filters are handled by the DSP of the baseband controller to calculate e.g. amplifications, sidetone, echo cancellation or noise suppression.

Full rate, half rate and enhanced full rate, speech and channel encoding including voice activity detection (VAD) and discontinuous transmission (DTX) and digital GMSK modulation are also performed on the GSM baseband processor.

### 3.7 SIM interface

The baseband processor has an integrated SIM interface compatible with the ISO 7816-3 IC Card standard. This is wired to the host interface (ZIF connector) in order to be adapted to an external SIM card holder.

Six pins on the ZIF connector are reserved for the SIM interface. Further to the five wire SIM interface according to GSM 11.11, the CCIN pin has been added. The CCIN pin serves to detect mechanically whether or not a card is inserted into the card holder. The default level of CCIN is low (internal pull down resistor, no card inserted). It must go high when the card is inserted.

To take advantage of this feature, an appropriate contact is required on the card holder. For example, this is true for the model supplied by Molex Deutschland GmbH, which was tested within the Siemens reference configuration (Molex ordering number 91228-0001). Ensure that the card holder on your application platform be wired to output a high signal when the SIM card is present.

*Note: Before removing the SIM card or inserting a new one be sure that the GSM engine has been powered down as described in Chapter 3.3.*

Table 9: Signal of the SIM interface

| Signal | Description   |
|--------|---|
| CCRST  | Chipcard reset, provided by baseband processor  |
| CCCLK  | Chipcard clock, various clock rates can be set in the baseband processor  |
| CCIO   | Serial data line, input and output.   |
| CCIN   | Input on the baseband processor for detecting the SIM in the holder; if the SIM is removed during operation the interface is shut down immediately to prevent destruction of the SIM. |
| CCVCC  | SIM supply voltage.   |
| CCGND  | Separate ground connection for SIM card to improve EMC  |

#### 3.7.1 Updating firmware over SIM interface

MC35 offers two different solutions for updating firmware. To download the software onto the module, you can either use the SIM interface or, if available on your application platform, the RS232 interface of the ZIF connector. To avail of the SIM option, you will need to purchase a special adapter named BB35 BootBox. Click <http://www.siemens.com/wm> for further details and ordering information.

### 3.8 Control signals

The following control signals are available (2.65V CMOS level).

#### 3.8.1 Inputs

Table 10: Input control signals of the MC35 module

| Function   | Pin   | Status         | Description                |
|------------|---|----------------|----------------------------|
| Ignition   | $\overline{\text{IGT}}$   | = falling edge | Power on MC35              |
|            |   | = 1            | No operation               |
|            | Active low $\geq$ 100ms (Open drain/collector driver required in cellular device application)<br>Note: If a charger and a battery is connected to the customer application the IGT signal must not be less than 1s. |                |                            |
| Power down | $\overline{\text{PD}}$  | = 0            | Power down GSM Engine MC35 |
|            |   | = 1            | No operation               |
|            | Active low $\geq$ 3.5s (Open drain/collector driver required in cellular device application). At the PD signal the watchdog signal of the GSM Engine can be traced (see description in Table 14).                   |                |                            |

### 3.8.2 Outputs

#### 3.8.2.1 Synchronization signal

The synchronization signal serves to indicate growing power consumption during the transmit burst. The signal is generated by the SYNC pin (pin number 32). Please note that this pin can adopt two different operating modes which you can select by using the AT^SSYNC command (mode 0 and 1). For details refer to the "AT Command Set".

To generate the synchronization signal the pin needs to be configured to mode 0 (= default). This setting is recommended if you want your application to use the synchronization signal for better power supply control. Your platform design must be such that the incoming signal accomodates sufficient power supply to the MC35 module if required. This can be achieved by lowering the current drawn from other components installed in your application. The characteristics of the synchronization signal are explained below.

Table 11: MC35 synchronization signal (if SYNC pin is set to mode 0 via AT^SSYNC)

| Function        | Pin  | Status | Description  |
|-----------------|------|--------|--|
| Synchronization | SYNC | = 0    | No operation   |
|                 |      | = 1    | Indicates increased power consumption during transmission. |

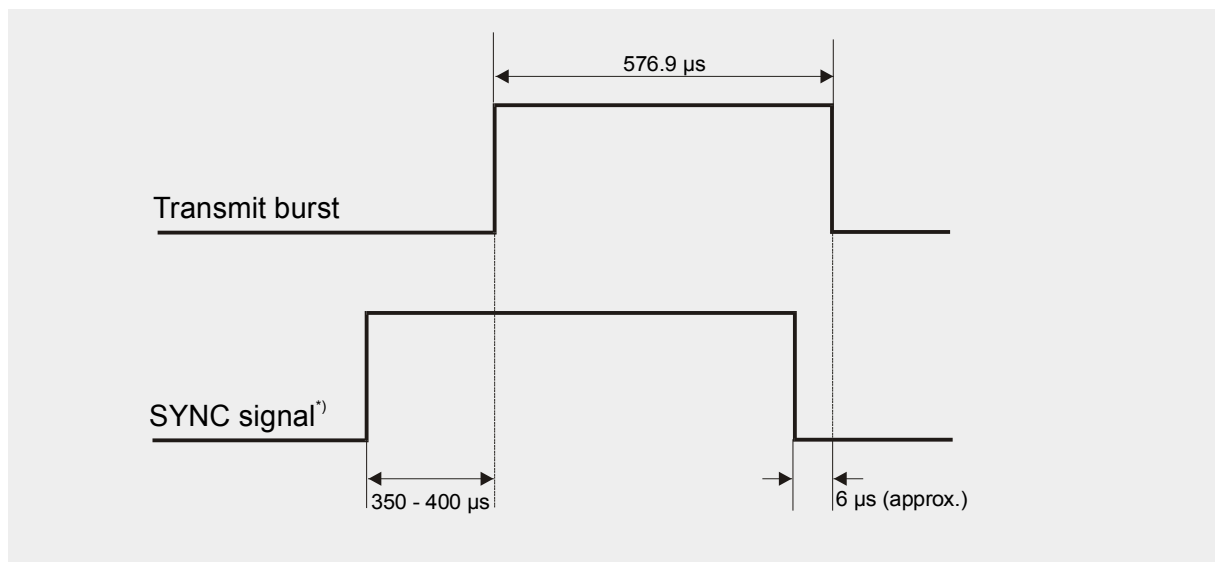


Figure 14: MC35 output control signals

<sup>\*)</sup> The duration of the SYNC signal is always equal, no matter whether the traffic or the access burst are active.

### 3.8.2.2 Using the SYNC pin to control a status LED

As an alternative to generating the synchronization signal, the SYNC pin can be used to control a status LED on your application platform.

To avail of this feature you need to set the SYNC pin to mode 1 by using the AT^SSYNC command. For details see the "AT Command Set".

When controlled from the SYNC pin the LED can display the following functions:

Table 12: Modes of the LED and associated functions

| LED mode                            | Function   |
|-------------------------------------|--|
| Off <sup>*)</sup>                   | MC35 is off or in Sleep mode   |
| 600 ms On / 600ms Off <sup>*)</sup> | No SIM card inserted or no PIN entered, or network search in progress, or ongoing user authentication, or network login in progress.   |
| 75ms On / 3s Off <sup>*)</sup>      | Logged to network (monitoring control channels and user interactions). No call in progress.  |
| On                                  | Depending on type of call:<br><i>Voice call:</i> Connected to remote party.<br><i>Data call:</i> Connected to remote party or exchange of parameters while setting up or disconnecting a call. |

<sup>\*)</sup> LED Off = SYNC pin low. LED On = SYNC pin high

To operate the LED a buffer, e.g. a transistor or gate, must be included in your application. A sample configuration can be gathered from Figure 15. Power consumption in the LED mode is the same as for the synchronization signal mode. For details see Table 14, pin number 32.

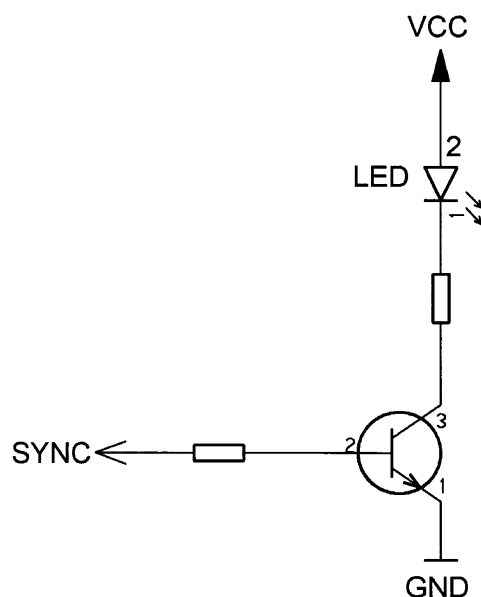


Figure 15: LED Circuit (Example)

### 3.8.2.3 Behavior of the RING0 line

The behavior of the RING0 line depends on the type of the call received.

- When a *voice call* comes in the RING0 line goes low for 1s and high for another 4s. Every 5 seconds the ring string is generated and sent over the RXD0 line. If there is a call in progress and call waiting is activated for a connected handset or handsfree device, the RING0 pin switches to ground in order to generate acoustic signals that indicate the waiting call.

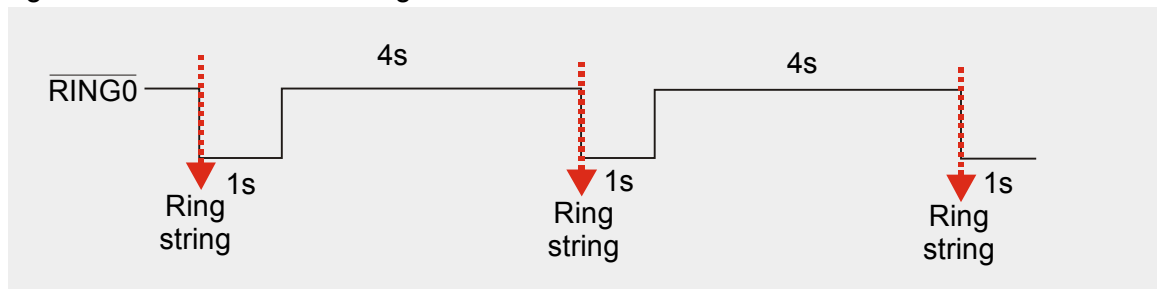


Figure 16: Incoming voice call

- Likewise, when a *Fax or data call* is received, RING0 goes low. However, in contrast to voice calls, the line remains low. Every 5 seconds the ring string is generated and sent over the RXD0 line.

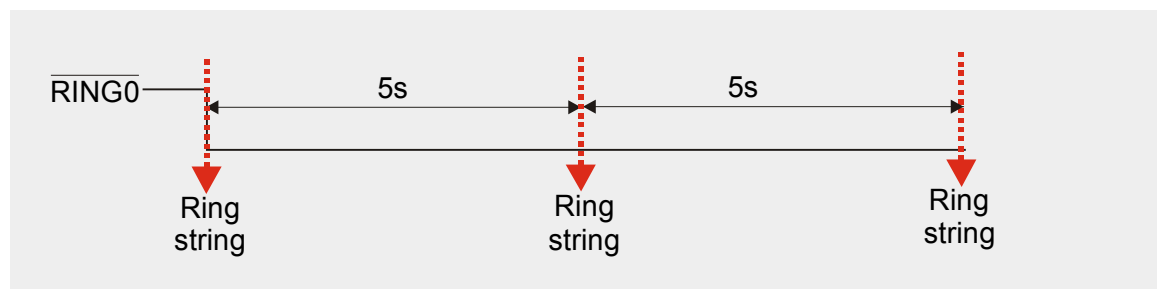


Figure 17: Incoming data call

- An incoming *SMS* can be indicated by an Unsolicited Result Code (URC) which causes the RING line to go low for 1 second only. Using the AT+CNMI command you can configure MC35 whether or not to send URCs upon the receipt of SMS. For instance, enter `AT+CNMI=1,1` to activate URCs for incoming short messages. For more details please refer the "MC35 AT Command Set".

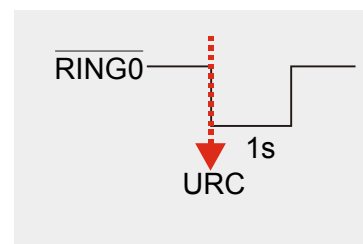


Table 13: MC35 ring signal

| Function        | Pin   | Status | Description   |
|-----------------|-------|--------|---|
| Ring indication | RING0 | = 0    | Indicates an incoming call.<br>Wakeup of cellular device application. |
|                 |       | = 1    | No operation  |

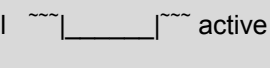
### 3.9 Pin assignment

Please note that the reference voltages listed below are the values measured directly on the MC35 module. They do not apply to the accessories connected.

Table 14: Pin assignment

| Function                                | Signal Name      | Pin No. | I/O | Signal Level  | Comment   |
|---|------------------|---------|-----|---|---|
| Power supply                            | VBATT+           | 1       | I/O | Input:<br>$V_{in} = 3.3V \dots 4.8V$<br><br>$I_{max} \leq 2A$<br><br>$I_{max}$ is valid only during uplink transmission timeslot (e.g. TALK mode: $I_{max}$ for $577\mu s$ every $4.616ms$ )<br><br>Output: only valid when charging            | Usage is mandatory<br><br>Five power supply pins have to be connected in parallel due to peak current up to 2A<br><br>Voltage must stay within the min/max values, including voltage drop, ripple, spikes. See also Table 23. |
|   |                  | 2       |     |   |   |
|   |                  | 3       |     |   |   |
|   |                  | 4       |     |   |   |
|   |                  | 5       |     |   |   |
|   | GND              | 6       | -   | Ground (0V)   |   |
|   |                  | 7       |     |   |   |
|   |                  | 8       |     |   |   |
|   |                  | 9       |     |   |   |
|   |                  | 10      |     |   |   |
| Charger                                 | POWER            | 11      | I   | $V_{in} = 5.5V \dots 8V$<br>$I_{max} = 500mA$<br>Internal Pull Down (100k $\Omega$ )  | If unused keep pin open   |
|   |                  | 12      |     |   |   |
| Supply voltage for external application | VDD              | 13      | O   | IDLE / TALK mode:<br>$V_{out} = 2.9V \pm 3\% @ 70mA$<br><br>$I_{max} = 70mA$<br><br>Power Down mode: $V_{out} = 0V$<br><br>$C_{load \ max, \ extern} = 1\mu F$  | If unused keep pin open<br><br>Voltage is applied 60ms – 100ms after IGT was driven low.  |
| Battery temperature                     | ACCU_TEMP        | 14      | I/O | External NTC: $R_{NTC} = 10k\Omega @ 25^{\circ}C \pm 3\%$ connected to GND<br><br>IDLE / TALK mode:<br>$V_{out, MEAS}(R_{NTC}=10k\Omega)=1.15V$<br><br>Power Down mode:<br>$V_{out} = 0V$ (internal Pull Down)                                  | If unused keep pin open. If used: external NTC should be installed inside or near battery pack enables the charging algorithm and delivers temperature values   |
| Ignition                                | $\overline{IGT}$ | 15      | I   | IDLE / TALK / Power Down mode:<br><br>$V_{in, \ high, \ min} = 2.0V$<br>$R_{pullup} = 200k\Omega$<br>$V_{low, \ max} = 0.45V @ I_{out} = 10\mu A$<br>$t_{low} \geq 100ms$ (see Chapter 3.3!)<br><br>Signal: falling edge and hold for $t_{low}$ | Usage is mandatory<br><br>Open drain/collector driver or a simple switch is required to pull down this pin to power on MC35.<br><br>Signal is low active.   |

| Function | Signal Name  | Pin No. | I/O | Signal Level   | Comment  |
|----------|--------------|---------|-----|--|--|
| RS232    | DSR0         | 16      | O   | IDLE / TALK mode:  | <p>Application interface to control MC35 via AT commands</p> <p>If unused keep output pins open and connect input pins to GND via 10kΩ.</p> <p>When a voice call comes in RING0 goes active low for 1s and inactive high for another 4s (alternating). An incoming data call also causes RING0 to go active low, but without changing to inactive high. See Chapter 3.8.2.3.</p> <p><u>DCD0</u> and <u>DTR0</u> lines are connected via internal clamp diodes to 2.65V and GND</p> |
|          | <u>RING0</u> | 17      | O   | Output:  |  |
|          | RxD0         | 18      | O   | $R_i = 1k\Omega$ (serial resistor)<br>$V_{out,low,max} = 0.2V @ I = 0.1mA$<br>$V_{out,high,min} = 2.25V @ I = -0.1mA$<br>$V_{out,high,max} = 2.76V$  |  |
|          | TxD0         | 19      | I   | Input:   |  |
|          | CTS0         | 20      | O   | $R_i \geq 1M\Omega$<br>$V_{in,low,min} = -0.3V, V_{i,l,max} = 0.5V$<br>$V_{in,high,min} = 1.95V, V_{i,h,max} = 3.3V$   |  |
|          | RTS0         | 21      | I   |  |  |
|          | DTR0         | 22      | I   |  |  |
|          | DCD0         | 23      | O   | Power Down mode: <ul style="list-style-type: none"> <li>• Signals are low active.</li> <li>• Be aware of backward supply effects at the <i>inputs</i> and <i>outputs</i></li> </ul>  |  |
| SIM      | CCIN         | 24      | I   | IDLE / TALK mode:<br>SIM contact (active high)<br>$R_{PD} = 100k\Omega$ (internal Pull Down resistor to GND)<br>$R_i = 10k\Omega$ (serial resistor)<br>$V_{in,low,max} = 0.4V$<br>$V_{in,high,min} = 2.15V, V_{i,h,max} = 3.3V$<br><br>Power Down mode:<br>Be aware of backward supply | <p><u>All</u> signals of the SIM interface are protected from electrostatic discharge with spark gaps to GND and clamp diodes to 2.9V and GND</p> <p>If a card is inserted CCIN has to be at high level</p> <p>If not used connect to CCVCC</p>  |
|          | CCRST        | 25      | O   | $R_i \sim 47\Omega$<br>External C = 1nF to CCGND required. This capacitor must be located close to the SIM card reader.  | <p>Usage is mandatory</p> <p>Signal levels according to GSM Rec. (2)</p> <p>FFC must not exceed 200mm to meet the timing requirements of GSM Rec. 11.10</p>  |
|          | CCIO         | 26      | I/O | Output:<br>$R_i \sim 220\Omega$ (serial resistor)<br>$V_{OL,max} = 0.2V$ at $I = 0.1mA$<br>$V_{OH,min} = 2.25V$ at $I = -0.1mA$<br>$V_{OH} = 2.76V$<br><br>Input:<br>$R_i \sim 10k\Omega$<br>$V_{iL,min} = -0.3V, V_{iL,max} = 0.5V$<br>$V_{iH,min} = 1.95V, V_{iH,max} = 3.3V$        |  |

| Function                               | Signal Name            | Pin No. | I/O | Signal Level  | Comment  |
|--|------------------------|---------|-----|---|--|
| SIM                                    | CCLK                   | 27      | O   | Output:<br>$R_i \sim 220 \Omega$ (serial resistor)<br>$V_{OL,max} = 0.2 \text{ V}$ at $I = 0.1 \text{ mA}$<br>$V_{OH,min} = 2.25 \text{ V}$ at $I = -0.1 \text{ mA}$<br>$V_{OH} = 2.76 \text{ V}$   |  |
|  | CCVCC                  | 28      | O   | $CCVCC_{min} = 2.84 \text{ V}$<br>$CCVCC_{max} = 2.96 \text{ V}$<br>$I_{max} = 20 \text{ mA}$<br><br>External $C \geq 200 \text{ nF}$ to CCGND is required. This capacitor must be located close to the SIM card reader.  | Usage is mandatory   |
|  | CCGND                  | 29      | O   | Ground (0V)   | Usage is mandatory. See Application note SIM Interface for details on grounding.   |
| RTC backup                             | VDDL                   | 30      | I/O | IDLE/TALK/Power Down mode if VBATT+ connected:<br>$V_{out} < V_{BATT+}$<br>$R_i = 1 \text{ k}\Omega$ (serial resistor)<br><br>PD mode if VBATT+ disconnected:<br>$V_{in} = 2.0 \text{ V} \dots 5.5 \text{ V}$<br>$I_{in,max} = 30 \mu\text{A}$  | If unused keep pin open (see chapter 3.4)  |
| Power down<br><br>(only for emergency) | $\overline{\text{PD}}$ | 31      | I/O | IDLE/ TALK mode input:<br>$V_{in,low,max} = 0.45 \text{ V}$ @ $I = 0.1 \text{ mA}$<br><br>input signal  active low $\geq 3.5 \text{ s}$<br><br>Watchdog output:<br>$V_{out,low} = 0.35 \text{ V}$ @ $0.01 \text{ mA}$<br>$V_{out,high} = 2.30 \text{ V}$ @ $-0.01 \text{ mA}$<br>$f_{out,min} = 0.16 \text{ Hz}$<br>$f_{out,typ} = 0.236 \text{ Hz}$<br>$f_{out,max} = 1.53 \text{ Hz}$ | If unused keep pin open<br><br>Open drain/collector driver or simple switch to GND required.<br><br>PD switches MC35 off. A low pulse at pin IGT resets MC35 and restarts the system.<br><br>The PD also indicates the internal watchdog function. |
| Synchronization                        | SYNC                   | 32      | O   | IDLE/ TALK mode:<br>$R_i = 1 \text{ k}\Omega$ (serial resistor)<br>$V_{out,low,max} = 0.2 \text{ V}$ @ $0.1 \text{ mA}$<br>$V_{out,high,min} = 2.25 \text{ V}$ @ $-0.1 \text{ mA}$<br>$V_{out,high,max} = 2.76 \text{ V}$<br><br>Power Down mode:<br>be aware of backward supply  | If unused keep pin open<br><br>Indication of increased current consumption during uplink transmission burst. Alternatively used to control status LED.   |

| Function        | Signal Name | Pin No. | I/O | Signal Level  | Comment   |
|-----------------|-------------|---------|-----|---|---|
| Audio Interface | EPP2        | 33      | O   | $R_i = 15\Omega$ , (30k $\Omega$ if not active)<br>$V_{omax} = 3.7V_{pp}$ , no load,<br>@ 3.14 dBm0:<br><br>$f = 1024\text{Hz}$ ,<br>audio mode = 6,<br>outBbcGain = 0,<br>outCalibrate = | If unused keep pin open   |
|                 | EPN2        | 34      | O   |   | 16384<br>Differential output, e.g. for external loud-speaker amplifier for handsfree operation                |
|                 | EPP1        | 35      | O   | $R_i = 15\Omega$ , (30k $\Omega$ if not active)<br>$V_{omax} = 3.7V_{pp}$ , no load,<br>@ 3.14 dBm0:<br><br>$f = 1024\text{Hz}$ ,<br>audio mode = 5,<br>outBbcGain = 0,<br>outCalibrate = | If unused keep pin open   |
|                 | EPN1        | 36      | O   |   | 16384<br>Differential output, e.g. for internal ear-piece   |
|                 | MICP1       | 37      | I   | $Z_i = 2k\Omega$<br>$V_{imax} = 1.03V_{pp}$<br>$V_{supply} = 2.65V$ ( 0V if off ), $R_{DC} = 4k\Omega$  | Keep unused interface open  |
|                 | MICN1       | 38      | I   |   | Balanced input with switchable microphone supply source, e.g. for internal microphone                         |
|                 | MICP2       | 39      | I   | $Z_i = 2k\Omega$<br>$V_{imax} = 1.03V_{pp}$<br>$V_{supply} = 2.65V$ ( 0V if off ), $R_{DC} = 4k\Omega$  | Keep unused interface open  |
|                 | MICN2       | 40      | I   |   | Balanced input with switchable microphone supply source, e.g. for external microphone for handsfree operation |

Explanation of signal names:

P = positive

N = negative

## 4 Radio interface

In transmit mode, the radio frequency part converts the I/Q baseband signals supplied by the baseband into a RF signal with characteristics as described by the GSM recommendation and which are then radiated by the antenna. In case of the receiving mode the radio part converts the RF signals supplied by the antenna into I/Q baseband signals which can then be further processed by the baseband.

The radio part is designed for dual band operation and can therefore serve the frequency bands GSM900 (including EGSM) and GSM1800. The following definitions have been made:

- The radio part can never transmit in both bands simultaneously.
- The radio part can never receive in both bands simultaneously.
- The monitor time slot can be selected independently of the frequency band.
- The transmitter and receiver never operate simultaneously.

### 4.1 Antenna interface (antenna reference point – ARP)

In order to connect the antenna MC35 uses a GSC connector. The interface is specified for an impedance of 50Ω with an SWR ≤ 2. MC35 is capable of withstanding a total mismatch at the antenna connector when transmitting at maximum RF power.

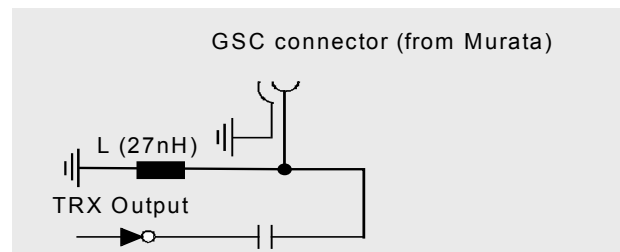


Figure 18: GSC connector circuit

To help you choose an appropriate antenna, Chapters 5.5 and 9 provide technical specifications and ordering information.

Table 15: Return loss

| State of the module | Return loss of the module | Required return loss of application |
|---------------------|---------------------------|-------------------------------------|
| receive             | 8dB min                   | 10dB min                            |
| transmit            | Not applicable            | 10dB min                            |
| idle                | 5dB max                   | Not applicable                      |

Table 16: Signals of GSC RF jack

| Signal name | Pin      | I/O | Description         | Parameter |
|-------------|----------|-----|---------------------|-----------|
| RF          | Internal | I/O | RF input and output | Z = 50 Ω  |
| GND         | External | X   | Ground connection   |           |

## 5 Physical characteristics

### 5.1 Exploded diagram

Figure 19 shows an exploded assembly drawing of the MC35 module.

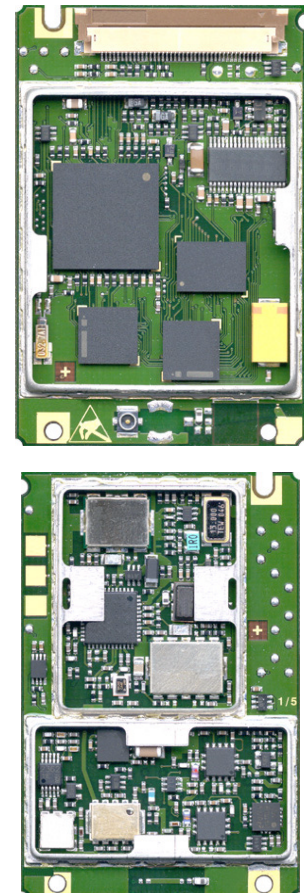
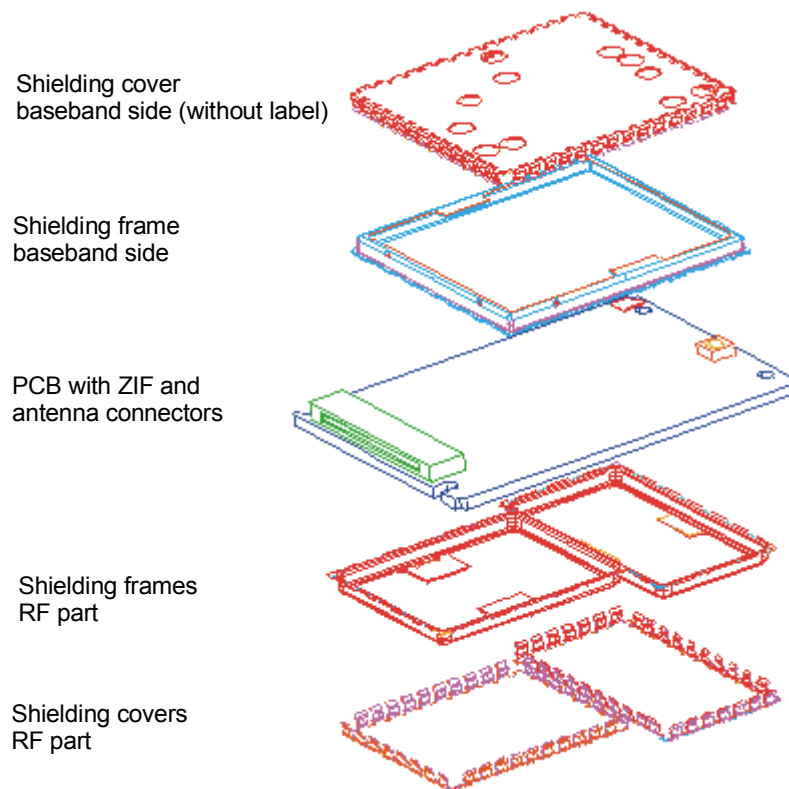


Figure 19: Exploded diagram of MC35

Figure 20: PCB of MC35 (top - baseband side, bottom - RF side)

## 5.2 Mechanical dimensions of MC35

Figure 21 shows the RF part of MC35 and provides an overview of the mechanical dimensions of the board. For further details see Figure 22.

Size:  $54.5_{\pm 0.2} \times 36_{\pm 0.2} \times 6.70_{\pm 0.35}$  mm

Weight: 17g

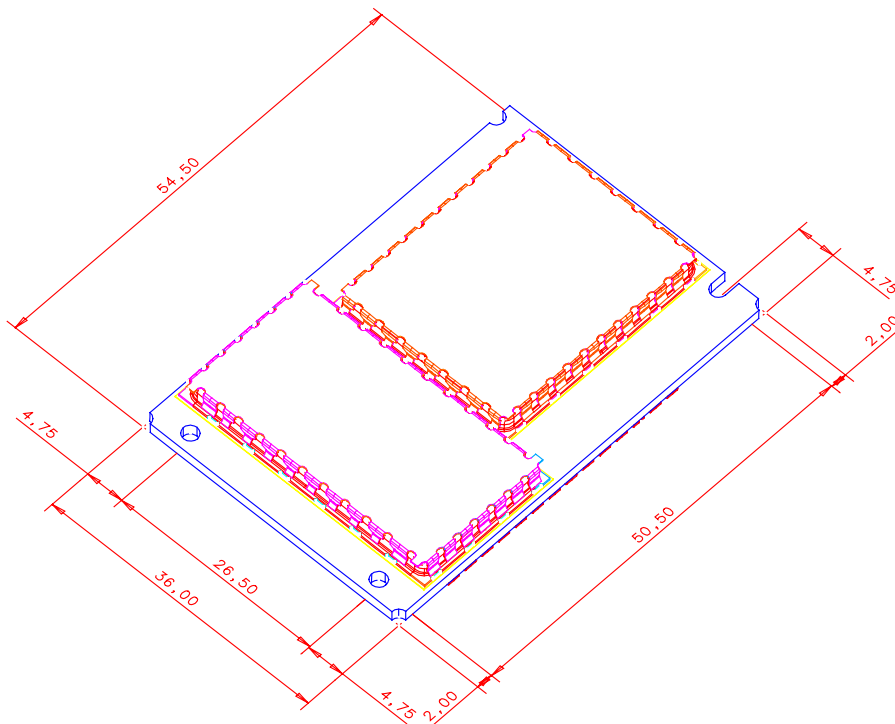
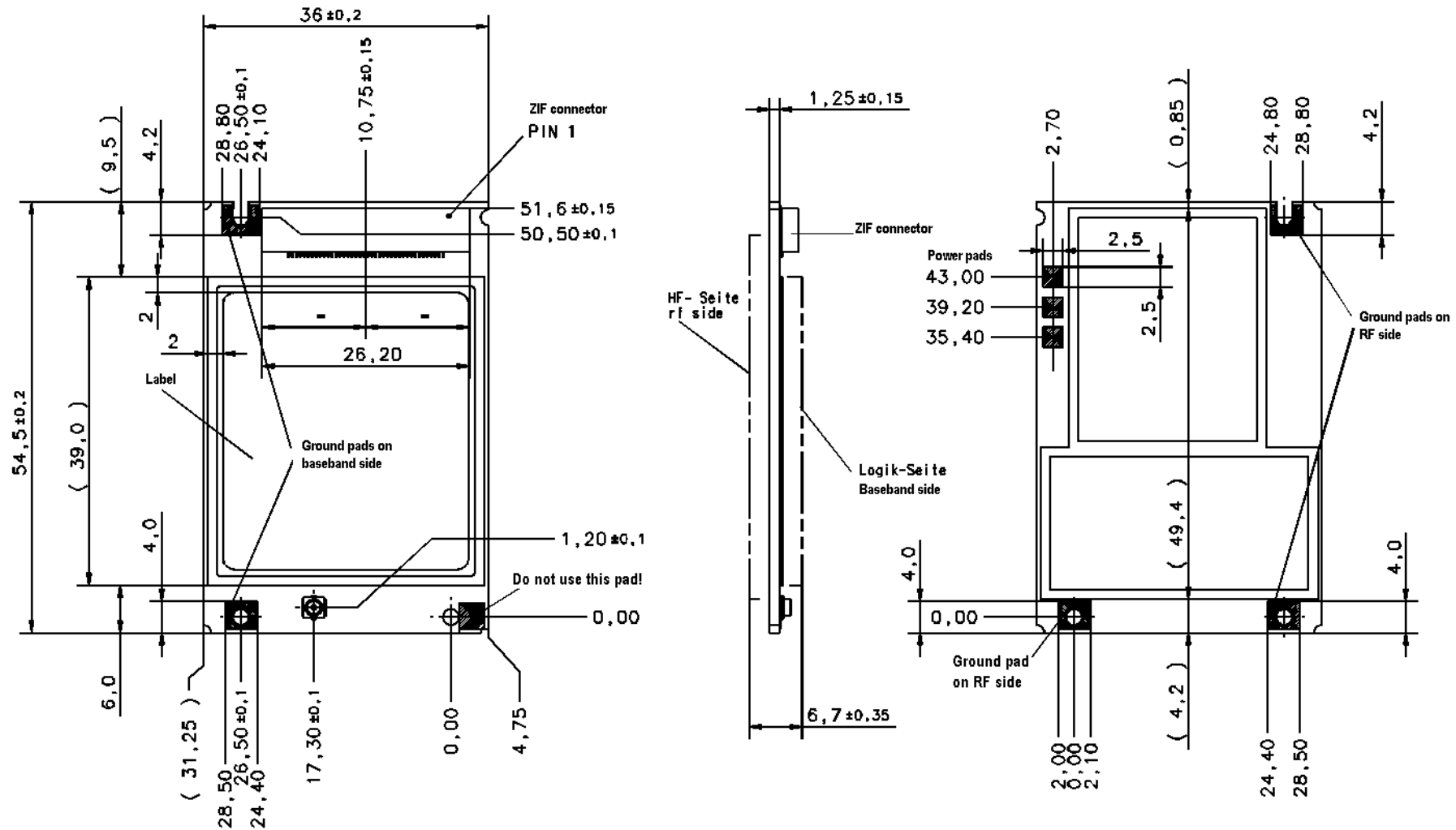


Figure 21: MC35 – view of RF side



0,00 = Reference point

All dimensions in millimeter

Figure 22: Mechanical dimensions of MC35

### 5.3 Mounting MC35 onto the application platform

For the cellular application to operate reliably it is essential that the MC35 module is securely attached to the host housing.

The MC35 board provides three mounting holes. To properly mount it to the host device you can use M1.6 or M1.8 screws plus suitable washers. The maximum diameter of the screw head incl. the washer must not exceed 4 mm.

Avoid placing the MC35 board tightly to the host device. Instead, it is recommended to set spacers between the MC35 module and the host device. If your design approach does not allow for spacers make sure the host device provides an opening for the RF part.

For ease of migration from TC35 or TC37 GSM engines, MC35 features the same dimensions. The ZIF connector, the RF connector and the mounting holes are located at the same coordinates.

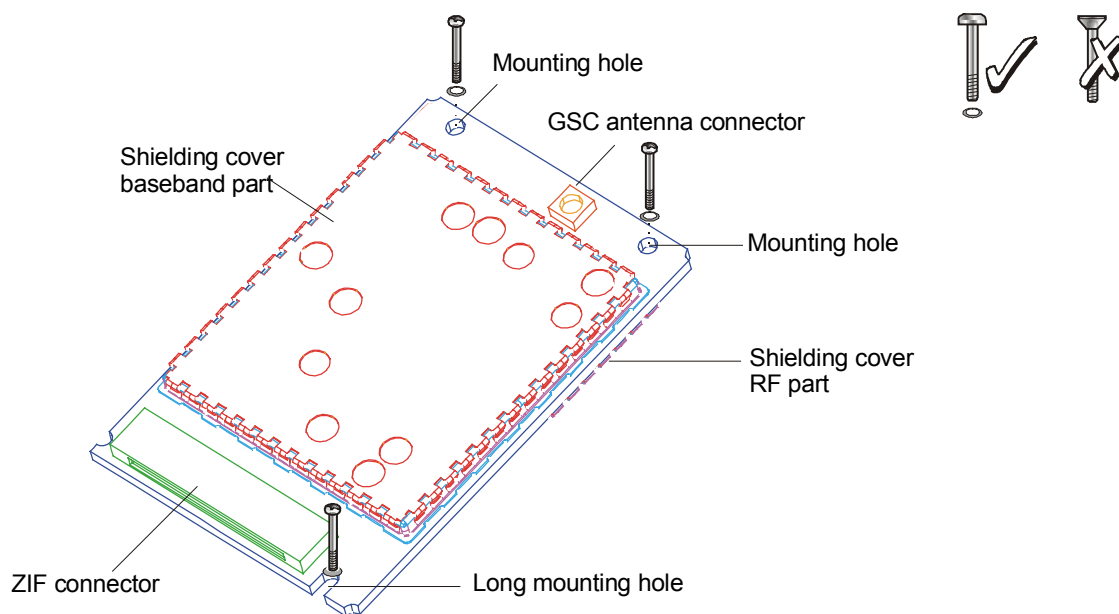


Figure 23: Mounting MC35 – view on baseband side

## 5.4 ZIF connector

This chapter provides specifications and handling instructions for the 40-pin ZIF connector and the Flat Flexible Cable (FFC) used to connect the GSM engine to the host application.

The ZIF (zero insertion force) design allows to easily fasten or remove the cable without the need for special tools. Simply insert the FFC cable into the open socket without using any pressure. Then carefully close the socket lid until the contacts of the socket grip the cable contacts.

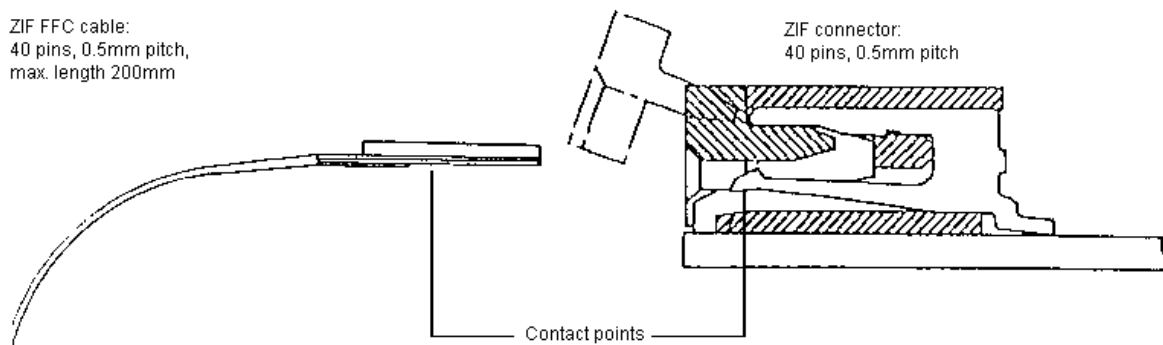


Figure 24: Connecting FFC cable to ZIF connector

Table 17: Electrical and mechanical characteristics of the ZIF connector

| Parameter                       | Specification (40 pin ZIF connector)                            |
|---------------------------------|---|
| Number of Contacts              | 40  |
| Quantity delivered              | 2000 Connectors per Tape & Reel                                 |
| Voltage                         | 50V   |
| Current Rating                  | 0.4A max per contact  |
| Resistance                      | 0.05 Ohm per contact  |
| Dielectric Withstanding Voltage | 200V RMS min  |
| Operating Temperature           | -40°C...+85°C   |
| Contact Material                | Phosphor bronze (tin-lead plated)                               |
| Insulator Material              | PPS, natural color  |
| Slider Material                 | PPS, natural color  |
| FFC/FPC Thickness               | 0.3mm ±0.05mm (0.012" ±0.002")                                  |
| Profile Height                  | 2.00mm  |
| Dimension A                     | 24  |
| Dimension B                     | 19.5  |
| Dimension C                     | 26.2  |
| Maximum connection cycles       | 50  |
| Cable                           | FFC (Flat Flexible Cable), max. length 200mm from SIM interface |

**5.4.1 Mechanical dimensions of the ZIF connector**

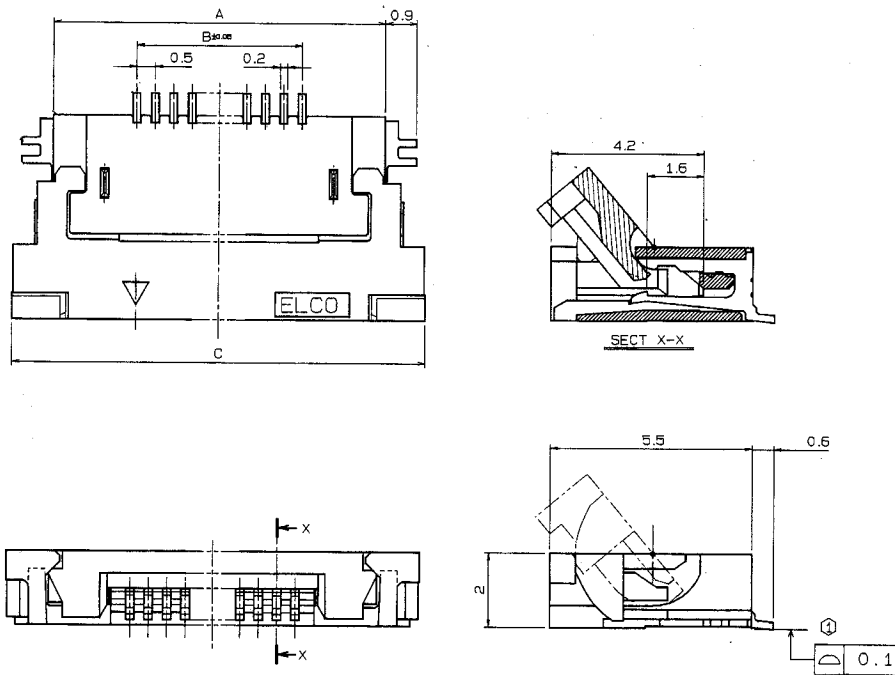


Figure 25: Mechanical dimensions of ZIF connector

**Pad-Layout**

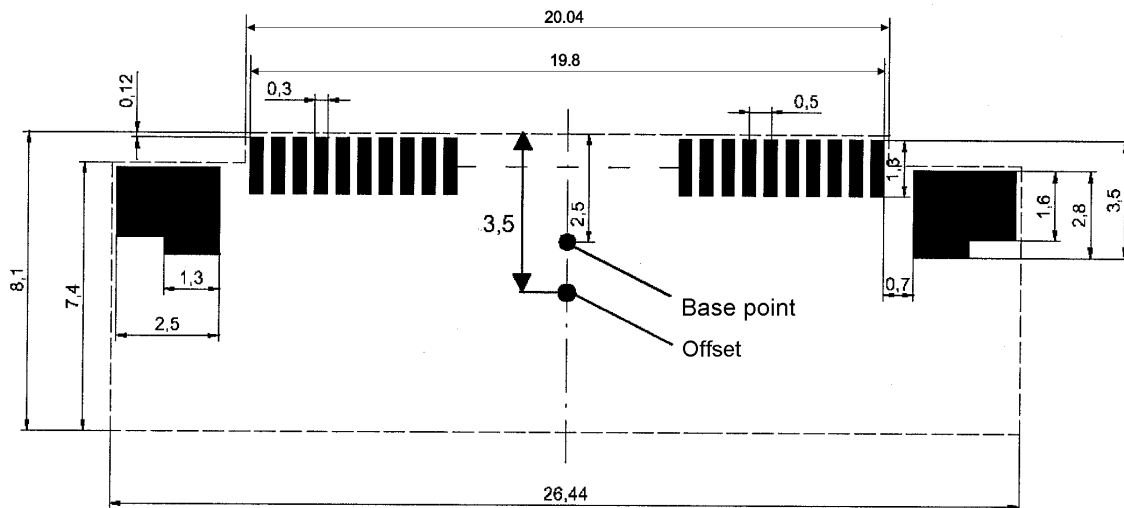


Figure 26: PCB ZIF connector

## 5.5 GSC antenna connector

MC35 uses a GSC antenna connector. Below please find brief ordering information to help you retrieve further details from the manufacturer MuRata, e.g. under <http://www.murata.com>.

| Description   | MuRata part number                     |
|---|--|
| Male connector mounted on TC35  | MM9329-2700                            |
| Matching female connectors suited for individual cable assembly <ul style="list-style-type: none"> <li>• Right-angle flexible cable</li> <li>• Right-angle flexible cable</li> <li>• Right-angle semirigid cable</li> </ul> | MXTK88xxxx<br>MXTK92xxxx<br>MXTK91xxxx |

The physical dimensions and maximum mechanical stress limits can be gathered from the table and the figures below. To securely fasten or remove the antenna cable MuRata recommends to use a special engagement/disengagement tool.

Table 18: Ratings and characteristics of the GSC antenna connector

| Item                  | Specification   |               |         |                   |              |             |                  |              |               |              |                     |      |
|-----------------------|---|---------------|---------|-------------------|--------------|-------------|------------------|--------------|---------------|--------------|---------------------|------|
| Frequency range       | DC to 6GHz  |               |         |                   |              |             |                  |              |               |              |                     |      |
| VSWR                  | 1.2 max. (DC to 3 GHz), 1.3 max. 3GHz to 6GHz)  |               |         |                   |              |             |                  |              |               |              |                     |      |
| Nominal impedance     | 50Ω   |               |         |                   |              |             |                  |              |               |              |                     |      |
| Temperature range     | -40°C to +90°C  |               |         |                   |              |             |                  |              |               |              |                     |      |
| Contact resistance    | 15mΩ max.   |               |         |                   |              |             |                  |              |               |              |                     |      |
| Insulation resistance | 500MΩ min.  |               |         |                   |              |             |                  |              |               |              |                     |      |
| Material and finish   | <table border="0"> <tr> <td>Material:</td> <td>Finish:</td> </tr> <tr> <td>• Center contact:</td> <td>Copper alloy</td> <td>Gold plated</td> </tr> <tr> <td>• Outer contact:</td> <td>Copper alloy</td> <td>Silver plated</td> </tr> <tr> <td>• Insulator:</td> <td>Engineering plastic</td> <td>None</td> </tr> </table> | Material:     | Finish: | • Center contact: | Copper alloy | Gold plated | • Outer contact: | Copper alloy | Silver plated | • Insulator: | Engineering plastic | None |
| Material:             | Finish:   |               |         |                   |              |             |                  |              |               |              |                     |      |
| • Center contact:     | Copper alloy  | Gold plated   |         |                   |              |             |                  |              |               |              |                     |      |
| • Outer contact:      | Copper alloy  | Silver plated |         |                   |              |             |                  |              |               |              |                     |      |
| • Insulator:          | Engineering plastic   | None          |         |                   |              |             |                  |              |               |              |                     |      |

**Note:** A 27nH inductor to ground provides additional ESD protection for the antenna connector. To protect the inductor from damage no DC voltage must be applied to the antenna circuit.

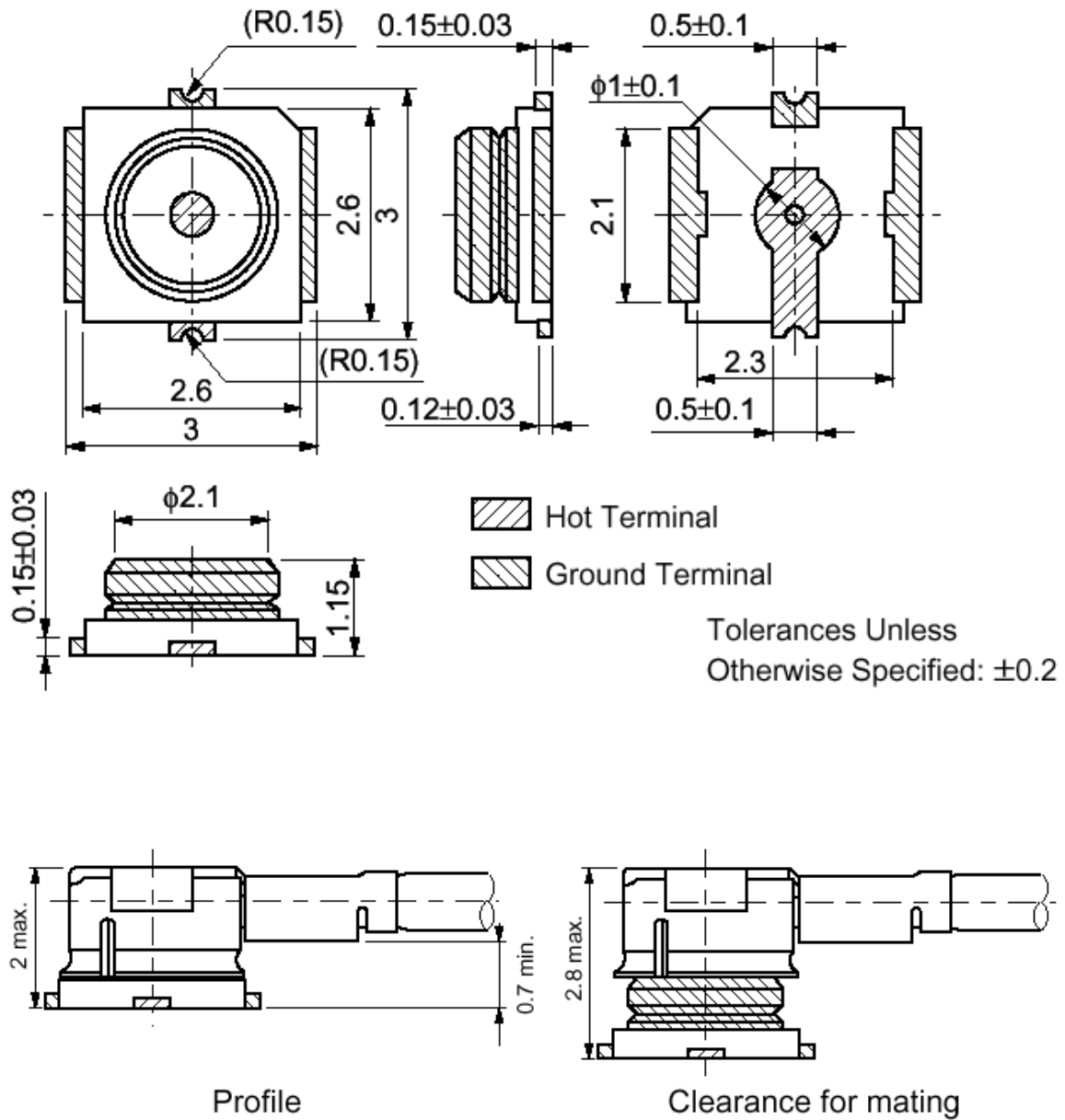


Figure 27: Mechanical dimensions of MuRata GSC connector (in mm)

Table 19: Stress characteristics of the GSC antenna connector

| Parameter  | Specification  |
|--|--|
| Connector durability   | 100 cycles of mating and withdrawal with a jig at 12 cycles/minute maximum |
| Engage force   | 30N max  |
| Disengage force  | 3N min, 30N max  |
| Angle of engagement  | 15 degree max  |
| Mechanical stress to connector   | See Figure 28 for details  |
| <ul style="list-style-type: none"> <li>• Stress to the housing: A and B: 4.9N max.</li> <li>• Stress to outer sleeve: C: 2.94N max and D: 1.96N max</li> <li>• Cable pull strength: E: 4.9N max</li> </ul> |  |

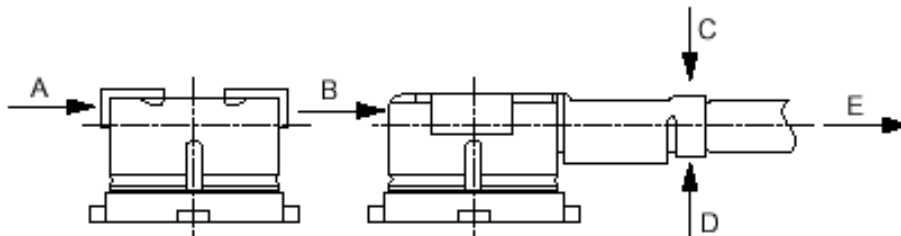


Figure 28: Maximum mechanical stress to the connector

The following figure illustrates the engagement/disengagement tool recommended by MuRata and provides instructions for proper use.

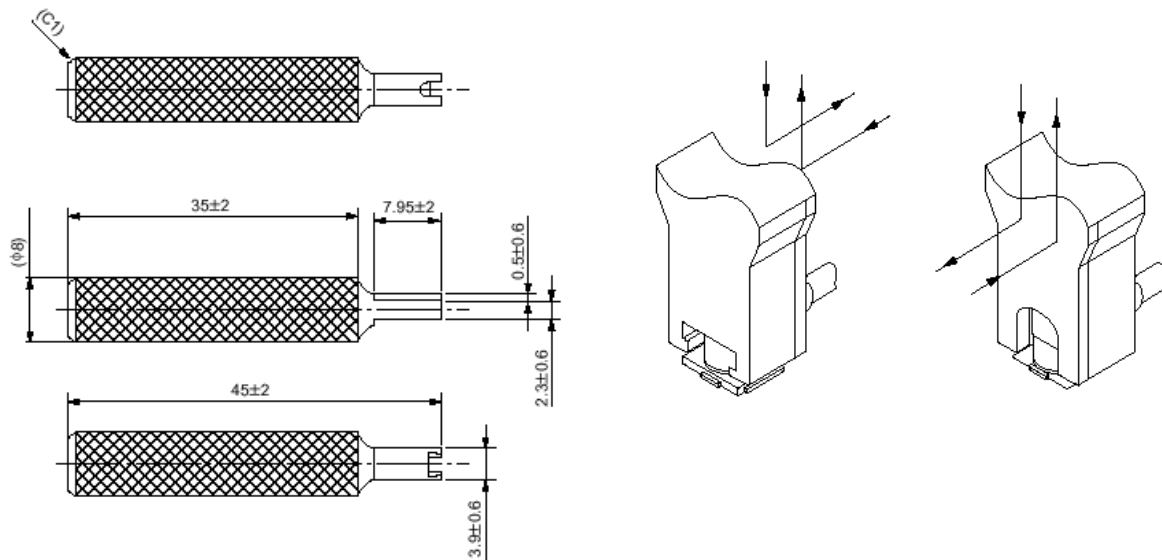


Figure 29: How to use MuRata tool

### 5.5.1 Using antenna cable from other manufacturers

For your product to meet individual design or technical requirements, you may decide to choose antenna equipment from suppliers other than MuRata.

When selecting a suitable antenna your considerations should also include the requirements of electromechanical valence. To achieve best performance it is essential to minimize the valence potential delta levels of dissimilar metal mating surfaces. Therefore the material of the antenna cable plug must be compatible with the material of the GSC receptacle on the GSM engine, i.e. it should belong to the same group in the electromechanical series. The material of the GSC connector on MC35 is specified in Table 18.

### 5.6 Position and dimension of power pads

As described in Chapter 3.2.3, MC35 can be powered across the ZIF connector and, in addition, from three contact pads. The power contact pads are placed on the RF part of the MC35 PCB. The position and the dimensions are shown in Figure 30.

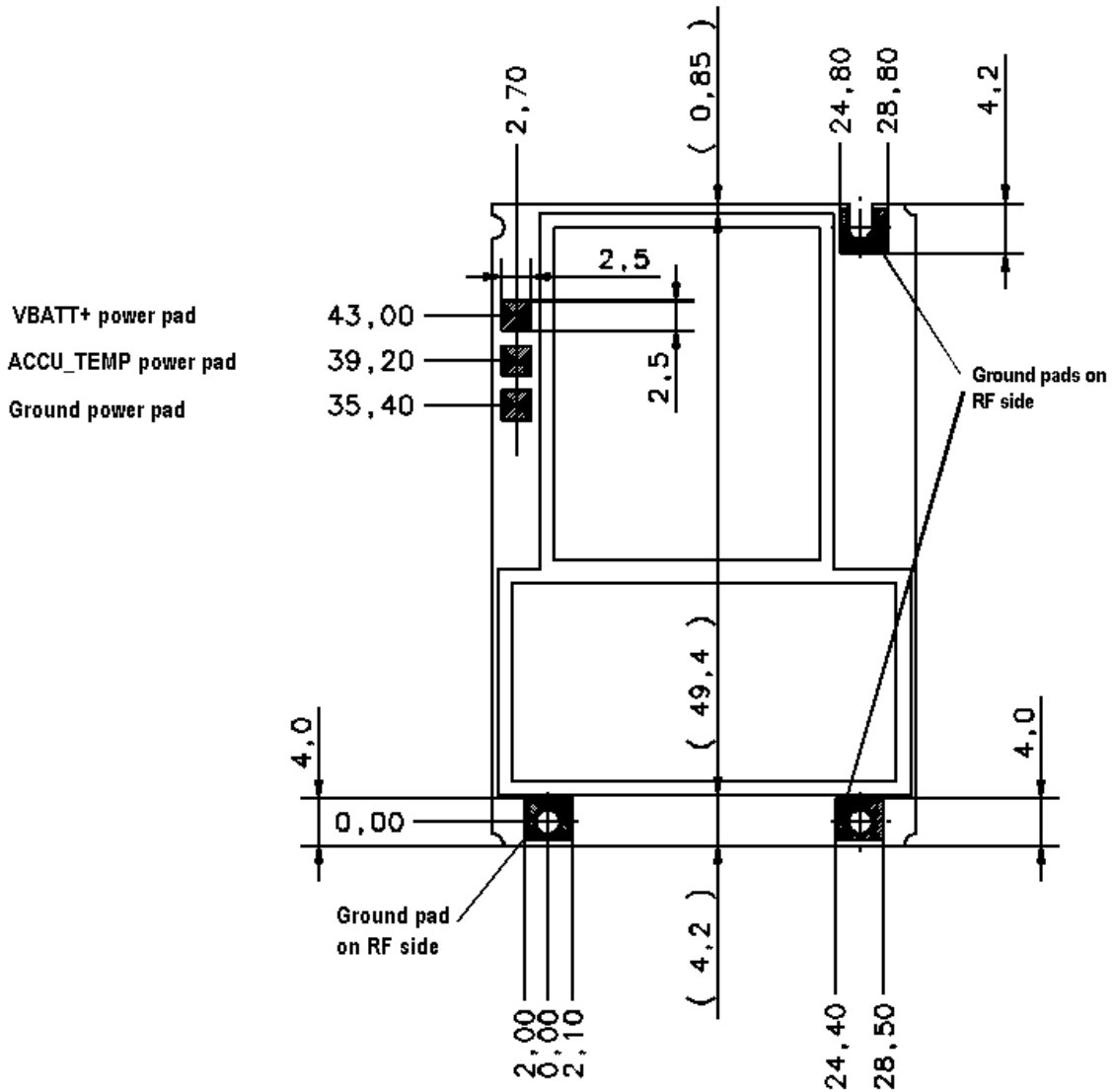


Figure 30: Power pads on the RF part of the MC35 PCB

## 6 Electrical, temperature and radio characteristics

### 6.1 Absolute maximum ratings

Absolute maximum ratings for supply voltage and voltages on digital and analog pins of GSM Engine MC35 are listed in Table 20. Exceeding these values will cause permanent damage to the GSM Engine MC35.

The safety status of the power supply has to be SELV (as defined by EN60950). The supply current must be limited according to Table 20.

Table 20: Absolute maximum ratings

| Parameter   | Min  | Max | Unit |
|---|------|-----|------|
| Supply voltage $V_{BATT+}$                          | 0    | 5.5 | V    |
| Peak current of power supply                        | 0    | 4.0 | A    |
| RMS current of power supply (during one TDMA-frame) | 0    | 0.7 | A    |
| Voltage on digital pins *)                          | -0.3 | 3.3 | V    |
| Voltage on analog pins *)                           | -0.3 | 3.0 | V    |
| Storage temperature                                 | -40  | +85 | °C   |

\*)Valid only in IDLE and TALK mode, if in Power Down mode absolute maximum ratings are  $\pm 0.25$  V.

### 6.2 Operating conditions

Table 21: Operating conditions

| Parameter                  | Min | Typ | Max | Unit |
|----------------------------|-----|-----|-----|------|
| Ambient temperature        | -20 | 25  | 55  | °C   |
| Supply voltage $V_{BATT+}$ | 3.3 | 4.2 | 4.8 | V    |

### 6.3 Temperature conditions

Table 22: Temperature conditions

| Parameter                                 | Min        | Typ | Max            | Unit |
|---|------------|-----|----------------|------|
| Ambient temperature (regarding GSM 11.10) | -20        | 25  | 55             | °C   |
| Restricted operation *)                   | -25 to -20 |     | 55 to 70       | °C   |
| Automatic switch off                      |            |     | $\geq 70^{**}$ | °C   |
| Storage temperature                       | -40        |     | +85            | °C   |

\*) MC35 works, but deviations from the GSM specification may occur.

\*\*\*) Limited performance if  $V_{BATT+ \max} \leq 4.0$ V and PCL5 is required at  $T_{amb \max} = 70^\circ$

## 6.4 Power supply ratings

Table 23: Power supply ratings

| Parameter           | Description  | Conditions  | Min | Typ | Max | Unit |
|---------------------|--|---|-----|-----|-----|------|
| V <sub>BATT+</sub>  | Supply voltage   | Reference point on VBATT+ contact pad<br><br>Voltage must stay within the min/max values, including voltage drop, ripple, spikes. | 3.3 | 4.2 | 4.8 | V    |
|                     | Voltage drop during transmit burst                               | Normal condition, power control level for P <sub>out max</sub>  |     |     | 400 | mV   |
| I <sub>BATT+</sub>  | Average supply current   | Power Down mode   |     | 50  | 100 | µA   |
|                     |  | SLEEP mode  |     | 3.5 |     | mA   |
|                     |  | IDLE mode GSM   |     | 10  | 20  | mA   |
|                     |  | TALK mode GSM   |     | 300 | 400 | mA   |
|                     |  | IDLE mode GPRS  |     | 10  | 20  | mA   |
|                     | DATA mode GPRS   |   | 360 | 480 | mA  |      |
|                     | Peak supply current (during 577µs transmission slot every 4.6ms) | Power control level for P <sub>out max</sub><br><br>I <sub>max</sub> @ antenna return loss =6dB                                   |     | 2   |     | A    |
| I <sub>CHARGE</sub> | Charging current   | Li-Ion battery pack   | 350 |     | 500 | mA   |
|                     | Trickle charging   | U <sub>battery</sub> 0...3.6V   |     |     | 9.0 | mA   |

### 6.4.1 Drop definition

During the transmission burst the supply voltage of MC35 can drop considerably, depending on the internal resistance of the external power supply. As specified, the supply voltage V<sub>BATT+</sub> must not fall below 3.3 V at any time, thus requiring an appropriate higher open-circuit voltage at MC35.

The drop of the supply voltage, generated by the serial resistance of the supply voltage connection, is not negligible. Peak currents of I = 2 A during the GSM transmission burst cause a supply voltage drop.

If your application incorporates a battery pack it is recommended to use the ZIF connector and the power contact pads in parallel. By connecting the battery power lines to the contact pads you can significantly reduce the total voltage drop caused across the ZIF-FFC-ZIF connection during transmit bursts. Note that the minimum supply voltage measured at the VBATT+ contact pad during TX bursts must not fall below 3.3 V, while the voltage drop must not exceed 400 mV. The power pads are located on the RF part of the PCB. See Chapters 3.2.1 and 5.6 for further details.

**Note:** *In order to reduce voltage drops during transmission choose cables (FFC) as short as possible and apply a low impedance power supply. The use of the ground pads further minimizes power losses.*

## 6.5 Electrical characteristics of the voiceband part

### 6.5.1 Setting audio parameters by AT commands

The audio modes 2 to 6 can be adjusted according to the parameters listed below. Each audio mode is assigned a separate set of parameters.

Table 24: Audio parameters adjustable by AT command

| Parameter                    | Influence to   | Range     | Gain range | Calculation                                   |
|------------------------------|--|-----------|------------|---|
| inBbcGain                    | MICP/MICN analogue amplifier gain of baseband controller before ADC  | 0...7     | 0...42dB   | 6dB steps                                     |
| inCalibrate                  | digital attenuation of input signal after ADC  | 0...32767 | -∞...0dB   | $20 * \log(\text{inCalibrate}/32768)$         |
| outBbcGain                   | EPP/EPN analogue output gain of baseband controller after DAC  | 0...3     | 0...-18dB  | 6dB steps                                     |
| outCalibrate[n]<br>n = 0...4 | digital attenuation of output signal after speech decoder, before summation of sidetone and DAC present for each volume step[n]  | 0...32767 | -∞...+6dB  | $20 * \log(2 * \text{outCalibrate}[n]/32768)$ |
| sideTone                     | digital attenuation of sidetone is corrected internally by outBbcGain to obtain a constant sidetone independent of output volume | 0...32767 | -∞...0dB   | $20 * \log(\text{sideTone}/32768)$            |

The following figure illustrates how the signal path can be influenced by varying the AT command parameters.

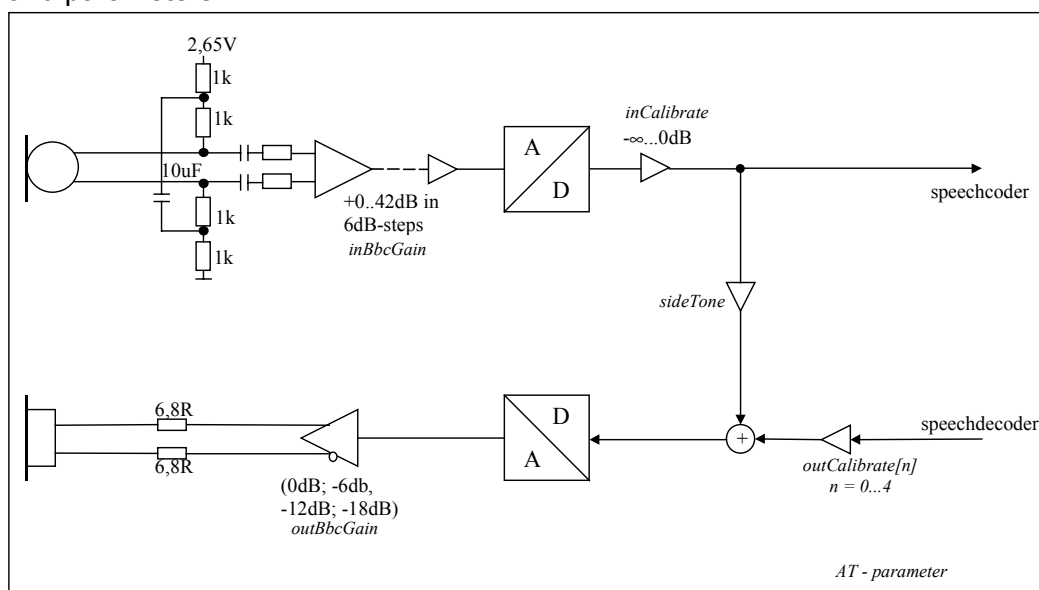


Figure 31: AT audio programming model

## 6.5.2 Characteristics of audio modes

The electrical characteristics of the voiceband part depend on the current audio mode set by the AT^SNFS command.

Table 25: Voiceband characteristics

| Audio mode no.<br>AT^SNFS=  | 1                     | 2                             | 3                           | 4                              | 5                             | 6                             |
|---|-----------------------|-------------------------------|-----------------------------|--------------------------------|-------------------------------|-------------------------------|
| Name  | Default Handset       | Basic Handsfree               | Headset                     | User Handset                   | Plain Codec 1                 | Plain Codec 2                 |
| Purpose   | DSB with M20T handset | Siemens Car Kit Portable      | Siemens Headset             | DSB with handset from customer | direct access to speech coder | direct access to speech coder |
| Gain setting via AT command   | NO                    | YES                           | YES                         | YES                            | YES                           | YES                           |
| MICPn/MICNn<br>EPPn/EPNn  | n=1                   | n=2                           | n=2                         | n=1                            | n=1                           | n=2                           |
| Supply  | ON                    | ON                            | ON                          | ON                             | OFF                           | OFF                           |
| Sidetone  | YES                   | NO                            | YES                         | YES                            | YES                           | YES                           |
| Volume control  | NO                    | YES                           | YES                         | YES                            | YES                           | YES                           |
| Limiter (receive)   | YES                   | YES                           | YES                         | YES                            | NO                            | NO                            |
| Compressor (receive)  | NO                    | YES <sup>*)</sup>             | NO                          | NO                             | NO                            | NO                            |
| AGC (send)  | NO                    | NO                            | YES                         | NO                             | NO                            | NO                            |
| Echo control (send)   | Suppression           | Cancellation + Suppression    | NO                          | Suppression                    | NO                            | NO                            |
| Noise suppression   | YES                   | YES                           | YES                         | YES                            | NO                            | NO                            |
| MIC input signal for 0dBm0 @ 1024 Hz (default gain)                               | 11.54 mV              | 91.9 mV                       | n.a. due to AGC             | 11.54 mV                       | 308.5 mV                      | 308.5 mV                      |
| EP output signal in mV eff. @ 0dBm0, 1024 Hz, no load (default gain); @ 3.14 dBm0 | 397.5 mV              | 561.4 mV default @ max volume | 288 mV default @ max volume | 397.5 mV default @ max volume  | 931.8 mV<br><br>3.7 Vpp       | 931.8 mV<br><br>3.7 Vpp       |
| Sidetone gain at default settings   | 22 dB                 | -∞ dB                         | n.a. due to AGC             | 22 dB                          | -∞ dB                         | -∞ dB                         |

All values are preliminary.

<sup>\*)</sup> Adaptive, receive volume increases with higher ambient noise level.

**Note:** With regard to acoustic shock, the cellular application must be designed to avoid sending false AT commands that might increase amplification, e.g. for a high sensitive earpiece. A protection circuit should be implemented in the cellular application.

### 6.5.3 Voiceband receive path

The values specified below were tested to 1kHz and 0dB gain stage, unless otherwise stated.

gs = 0dB means audio mode = 5 for EPP1 to EPN1 and 6 for EPP2 to EPN2, inBbcGain= 0, inCalibrate = 32767, outBbcGain = 0, OutCalibrate = 16384, sideTone = 0.

Table 26: Voiceband receive path

| Parameter   | Min  | Typ | Max  | Unit | Test condition / remark   |
|---|------|-----|------|------|---|
| Differential output voltage (peak to peak)                        | 3.33 | 3.7 | 4.07 | V    | from EPPx to EPNx<br>gs = 0dB @ 3.14 dBm0<br>no load                |
| Differential output gain settings (gs) at 6dB stages (outBbcGain) | -18  |     | 0    | dB   |   |
| fine scaling by DSP (outCalibrate)                                | -∞   |     | 0    | dB   |   |
| Output differential DC offset                                     |      |     | 100  | mV   | gs = 0dB, outBbcGain = 0 and -6dB                                   |
| Differential output resistance                                    | 13   | 15  |      | Ω    | from EPPx to EPNx   |
| Absolute gain accuracy  |      |     | 0.8  | dB   | Variation due to change in temperature and life time                |
| Attenuation distortion  |      |     | 1    | dB   | for 300...3900Hz,<br>@ EPPx/EPNx (333Hz) /<br>@ EPPx/EPNx (3.66kHz) |
| Out-of-band discrimination  | 60   |     |      | dB   | for $f > 4$ kHz with in-band test signal@ 1kHz and 1kHz RBW         |

gs = gain setting

### 6.5.4 Voiceband transmit path

The values specified below were tested to 1kHz and 0dB gain stage, unless otherwise stated.

Audio mode = 5 for MICP1 to MICN1 and 6 for MICP2 to MICN2, inBbcGain= 0, inCalibrate = 32767, outBbcGain = 0, OutCalibrate = 16384, sideTone = 0

Table 27: Voiceband transmit path

| Parameter  | Min                  | Typ                  | Max                  | Unit       | Test condition/Remark                               |
|--|----------------------|----------------------|----------------------|------------|---|
| Input voltage (peak to peak)<br>MICP1 to MICN1, MICP2 to MICN2 |                      |                      | 1.03                 | V          |   |
| Input amplifier gain in 6dB steps (inBbcGain)                  | 0                    |                      | 42                   | dB         |   |
| fine scaling by DSP (inCalibrate)                              | $-\infty$            |                      | 0                    | dB         |   |
| Input impedance  |                      | 2.0                  |                      | k $\Omega$ |   |
| Microphone supply voltage ON<br>Ri = 4k $\Omega$               | 2.57<br>2.17<br>1.77 | 2.65<br>2.25<br>1.85 | 2.73<br>2.33<br>1.93 | V          | no supply current<br>@ 100 $\mu$ A<br>@ 200 $\mu$ A |
| Microphone supply voltage OFF ;<br>Ri = 4k $\Omega$            |                      | 0                    |                      | V          |   |
| Microphone supply in power down mode                           |                      |                      |                      |            | see Figure 32                                       |

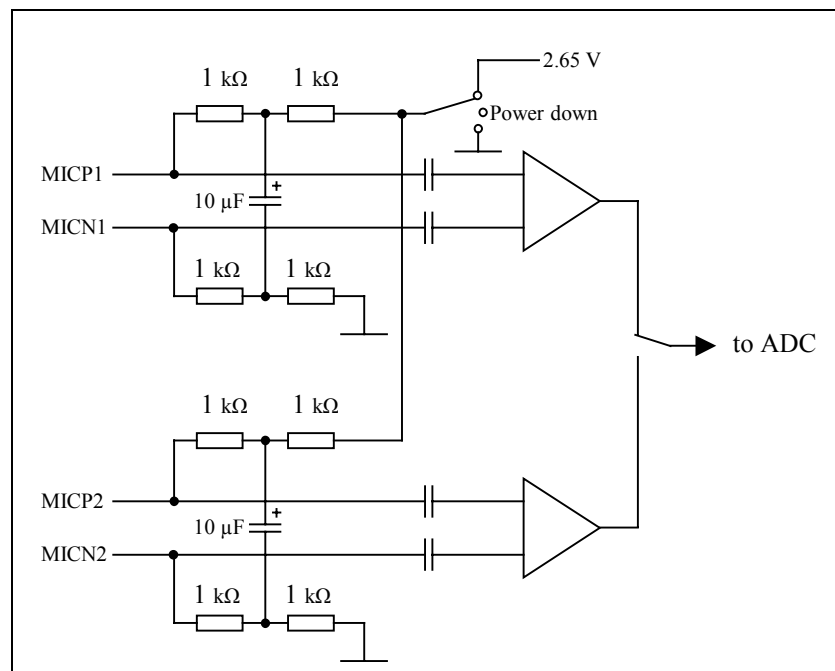


Figure 32: Structure of audio inputs

## 6.6 Air interface

Table 28: Air Interface

| Parameter   |           | Min              | Typ   | Max  | Unit |
|---|-----------|------------------|-------|------|------|
| Frequency range<br>Uplink (MS → BTS)                    | E-GSM 900 | 880              |       | 915  | MHz  |
|   | GSM 1800  | 1710             |       | 1785 | MHz  |
| Frequency range<br>Downlink (BTS → MS)                  | E-GSM 900 | 925              |       | 960  | MHz  |
|   | GSM 1800  | 1805             |       | 1880 | MHz  |
| RF power @ ARP with 50Ω load                            | E-GSM 900 | 31               | 33    |      | dBm  |
|   | GSM 1800  | 28               | 30    |      | dBm  |
| Number of carriers                                      | E-GSM 900 |                  | 174   |      |      |
|   | GSM 1800  |                  | 374   |      |      |
| Duplex spacing  | E-GSM 900 |                  | 45    |      | MHz  |
|   | GSM 1800  |                  | 95    |      | MHz  |
| Carrier spacing   |           |                  | 200   |      | kHz  |
| Multiplex, Duplex                                       |           | TDMA / FDMA, FDD |       |      |      |
| Time slots per TDMA frame                               |           |                  | 8     |      |      |
| Frame duration  |           |                  | 4.615 |      | ms   |
| Time slot duration                                      |           |                  | 577   |      | μs   |
| Modulation  |           | GMSK             |       |      |      |
| Receiver input sensitivity @ ARP<br>BER Class II < 2.4% | E-GSM 900 |                  | -105  | -102 | dBm  |
|   | GSM 1800  |                  | -105  | -102 | dBm  |

## 6.7 Electrostatic discharge

The GSM engine is not protected against Electrostatic Discharge (ESD) in general. Consequently, it is subject to ESD handling precautions that typically apply to ESD sensitive components. Proper ESD handling and packaging procedures must be applied throughout the processing, handling and operation of any application that incorporates a MC35 module.

Despite of this, the antenna port, the SIM interface, the ACCU\_TEMP port, the POWER port and the battery lines are equipped with spark gaps and clamp diodes to protect these lines from overvoltage. For all the other ports, ESD protection must be implemented on the application platform that incorporates the GSM engine.

MC35 has been tested and found to comply with the EN 61000-4-2 directive. The measured values can be gathered from the following table.

Table 29: Measured electrostatic values

| Pin No. | Signal name             | Contact discharge (environment) | Air discharge (directly to MC35) |
|---------|-------------------------|---------------------------------|----------------------------------|
| 1 - 5   | VBATT+                  | >4kV                            | 8kV                              |
| 6 - 10  | GND                     | >4kV                            | 8kV                              |
| 11 - 12 | POWER                   | >4kV                            | 8kV                              |
| 13      | VDD                     | >4kV                            | 1kV                              |
| 14      | ACCU_TEMP               | >4kV                            | 8kV                              |
| 15      | $\overline{\text{IGT}}$ | >4kV                            | 1kV                              |
| 16 - 23 | RS232 signals           | >4kV                            | 1kV                              |
| 24 - 29 | SIM signals             | >4kV                            | 8kV                              |
| 30      | VDDL <sub>P</sub>       | >4kV                            | 1kV                              |
| 31      | $\overline{\text{PD}}$  | >4kV                            | 1kV                              |
| 32      | SYNC                    | >4kV                            | 1kV                              |
| 33 - 40 | Audio                   | >4kV                            | 1kV                              |
| Antenna | RF GND                  | >4kV                            | 8kV                              |

*Note: Please note that the values may vary with the individual application design. For example, it matters whether or not the application platform is grounded over external devices like a computer or other equipment, such as the Siemens reference application described in Chapter 8.*

*The antenna connector is ESD protected by a 27nH inductor to ground. Therefore, no DC voltage must be applied to the antenna circuit in order to protect the inductor from damage (see Chapters 4.1 and 5.5).*

## 7 Using MC35 in conjunction with the DSB35 Support Box

The DSB35 Support Box is an evaluation kit designed to test and type approve Siemens cellular engines and provide a sample configuration for application engineering.

To take advantage of the evaluation kit please consider the following requirements specific to MC35. For further operating instructions and a detailed hardware interface description refer to the manual supplied with the DSB35 Support Box.

If you would like to purchase the DSB35 Support Box contact your local Siemens dealer. See Chapter 9 for ordering information.

### 7.1 Type approval requirements

Old versions of the DSB35 Support Box (e.g. supplied for TC35 evaluation) can be used to test and evaluate MC35 applications, but are not suited for type approval.

**Note:**

*If a configuration submitted for type approval includes a DSB35 Support Box, ensure that you use a model as per the new serial number. The number is printed on a label on the back of the DSB35 Support Box casing.*

|   |  |
|---|--|
| Old DSB35 version (not for MC35 type approval)    | S30880-S8101-A10-1<br>S30880-S8101-A10-2 |
| New DSB35 version (suited for MC35 type approval) | S30880-S8101-A10-3                       |

### 7.2 Power supply requirements

#### 7.2.1 Power supply sources

Applications that incorporate MC35 and a DSB35 Support Box must be powered from a *laboratory power supply*, regardless of the operating mode. The laboratory PSU is specified in the DSB35 manual (supply voltage 10V  $\pm$ 1V, maximum current 1A, compliant with EN 60950). The *plug-in PSU* delivered with DSB35 is intended only to test and evaluate the charging procedures of the battery pack. See also Chapter 7.3.

**Note:**

*The laboratory PSU connects to the 4mm X1404 and X1405 jacks illustrated in Figure 33.*

- To ensure that DSB35 and MC35 are powered from the laboratory PSU (normal operation, i.e. no battery charge and discharge test) set the X1300 toggle switch to "down" position.*
- To evaluate charging and discharging characteristics turn the X1300 toggle switch "up". In this case the laboratory PSU supplies only the DSB35 board.*

*The length of the DC connection wires between DSB35 and your power supply sources must not exceed 3m.*

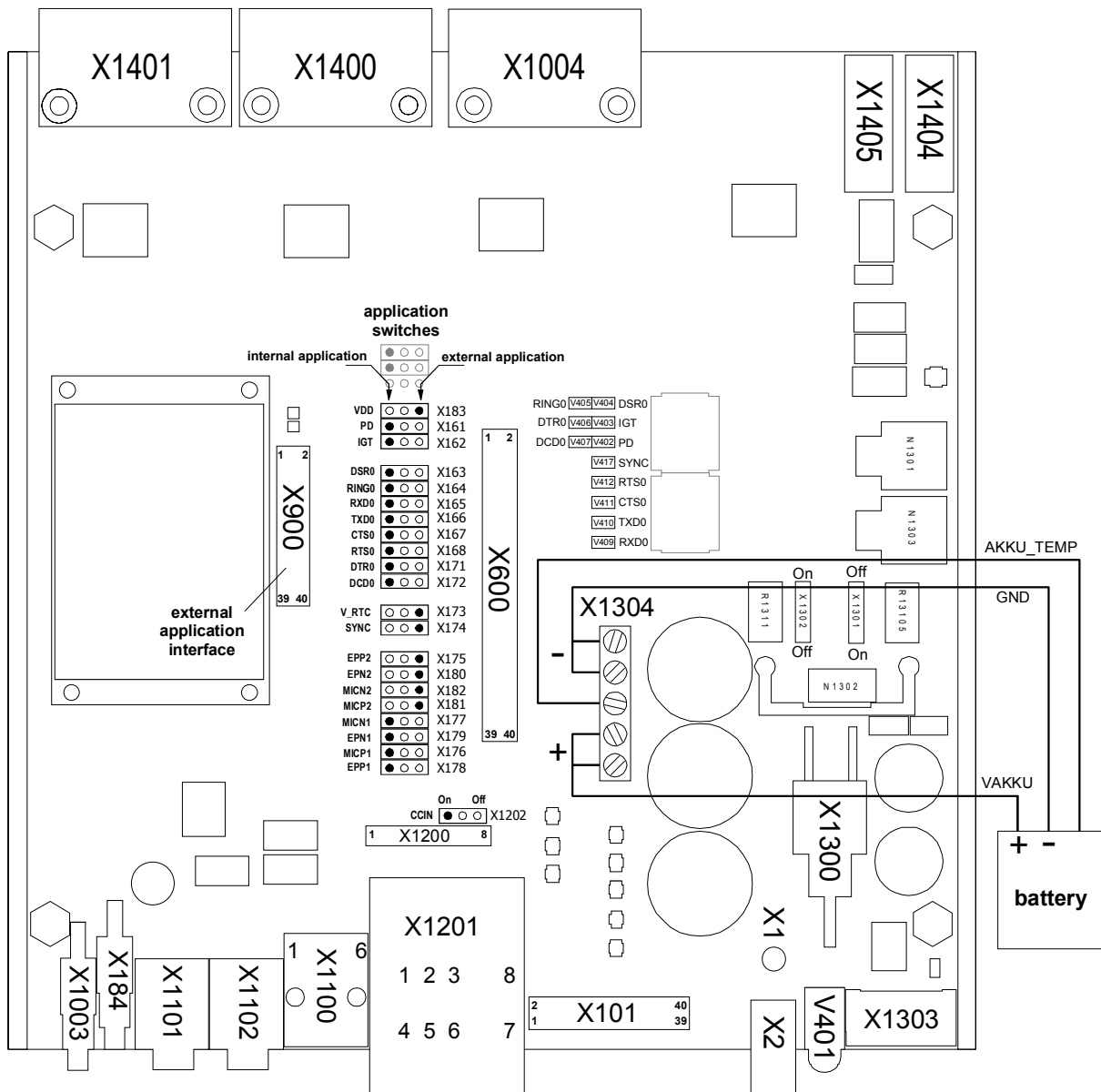


Figure 33: DSB35 board interfaces

## 7.2.2 Adjusting supply voltage

The DSB35 Support Box supplies a voltage ( $V_{BATT+}$ ) of up to 5.75V. To operate MC35 the voltage generated by the DSB board must be limited to 4.8V.

To vary the supply voltage the DSB board uses the two R1311 and R1305 potentiometers. Both can be easily adjusted with the X1301 and X1302 slide switches and a screw on each potentiometer. The position of the switches and the potentiometers can be gathered from Figure 33. For further details on the slide switches and the generated supply voltage please refer to the DSB35 manual.

Factory setting of the slide switches is 4.2V: X1301 = OFF and X1302 = ON.

**Note:**

*Follow these steps to adjust the supply voltage required for MC35.*

- 1. Set the slide switches: X1301 = OFF and X1302 = OFF. This is equivalent to  $V_{BATT+}$  5.5V.*
- 2. To reduce the supply voltage from 5.5V to 4.8V use a screw driver and turn the screw of R1311 until the supply voltage is 4.8V. Use the test points of the X600 connector to measure the generated voltage.*

### 7.3 Verifying charge and discharge time

The plug-in PSU supplied with the DSB35 board can be used to charge lithium-ion batteries.

**Note:**

*The internal electronic of the DSB35 Board affects the duration of charging and discharging. Your most effective approach to testing and verifying the charge and discharge time is, therefore, to make the measurements directly on your application platform, excluding the DSB35 board.*

## 8 Reference Approval

### 8.1 Reference Equipment

MC35 has been approved to satisfy all the requirements of GSM Phase 2/2.

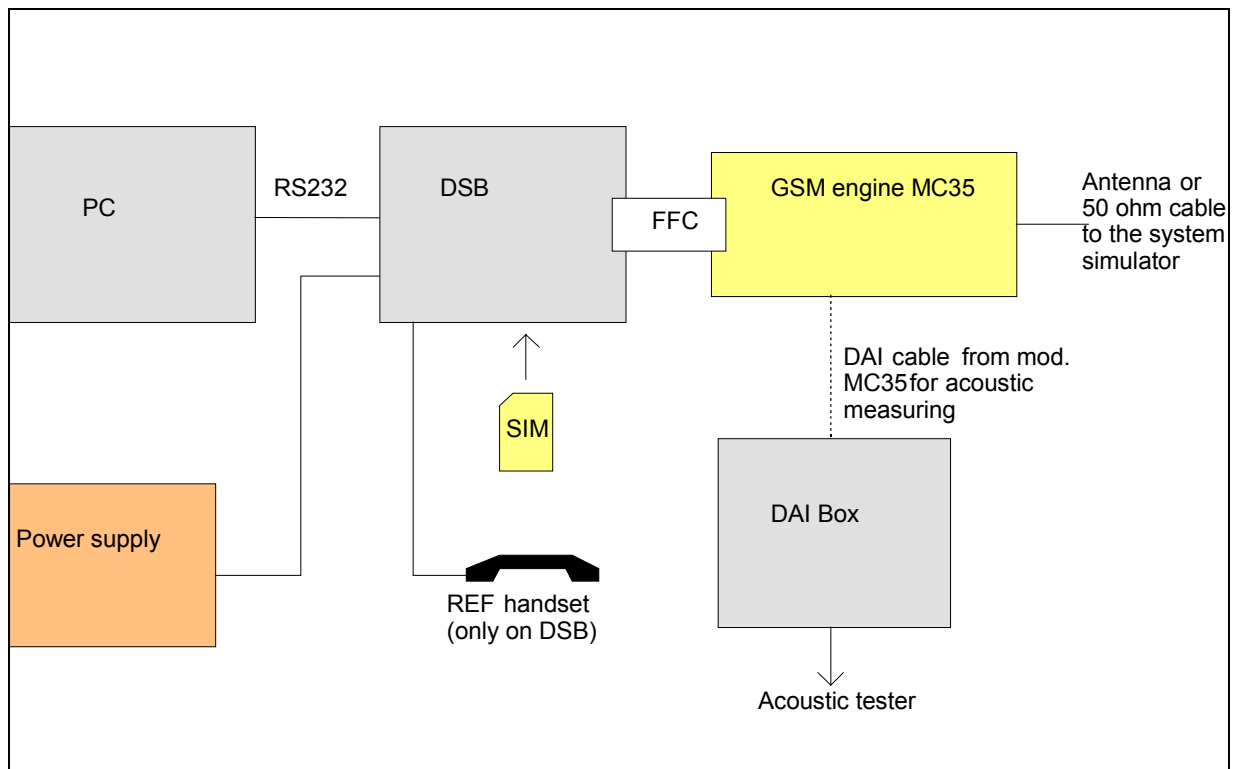


Figure 34: Reference Equipment for Approval

Referred to as "GSM terminal equipment" the reference configuration consists of the following components:

- Siemens MC35 cellular engine
- Development Support Box (DSB)
- SIM card reader integrated on the DSB
- Handset Votronic standard handset type HH-V0-30.1
- PC as MMI

For Siemens MC35, an IMEI number contingent has been reserved for the basic approval of the reference configuration. It will also apply to later approvals of customer configurations incorporating MC35 modules.

Approved Siemens MC35 configurations are recorded in the approval documentation. Later enhancements and modifications beyond the certified configuration require extra approvals. Each supplementary approval process includes submittal of the technical documentation as well as testing of the changes made. The relevant test applications for supplementary approvals should be agreed upon with Siemens.

## 9 Accessory list for MC35

Table 30: List of accessories

| Description  | Supplier | Parts number (supplier)  |
|--|----------|--|
| <b>Card holder SIM</b>   | Molex    | 91228  |
| <b>Ejector Type SIM</b>  |          | 91236  |
| <b>ZIF connector</b>   | AVX      | 04 6240 040 003 800  |
| <b>Flat cable for ZIF connector</b><br>(cable 160 mm)<br>(cable 80 mm) | Axon     | FFC 0.50 A 40 / 0160 K4.0-4.0-08.0-08.0SABB<br>FFC 0.50 A 40 / 0080 K4.0-4.0-08.0-08.0SABB |
| <b>RF cable GSC-GSC</b><br>(cable 50 mm)<br>(cable 100 mm)             | Murata   | MXTK 88 TK 0500<br>MXTK 88 TK 1000   |
| <b>GSC connector</b>   | Murata   | MM9329-2700 TB2  |
| <b>Handset</b>   | Votronic | HH-SI-30.3/V1.1/0  |
| <b>Siemens Car Kit Portable</b>  | Siemens  | Siemens ordering number<br>L36880-N3015-A117   |
| <b>DSB35 Support Box</b>   | Siemens  | Siemens ordering number<br>L36880-N8101-A100-3   |
| <b>BB35 Bootbox</b>  | Siemens  | Siemens ordering number<br>L36880-N8102-A100-1   |